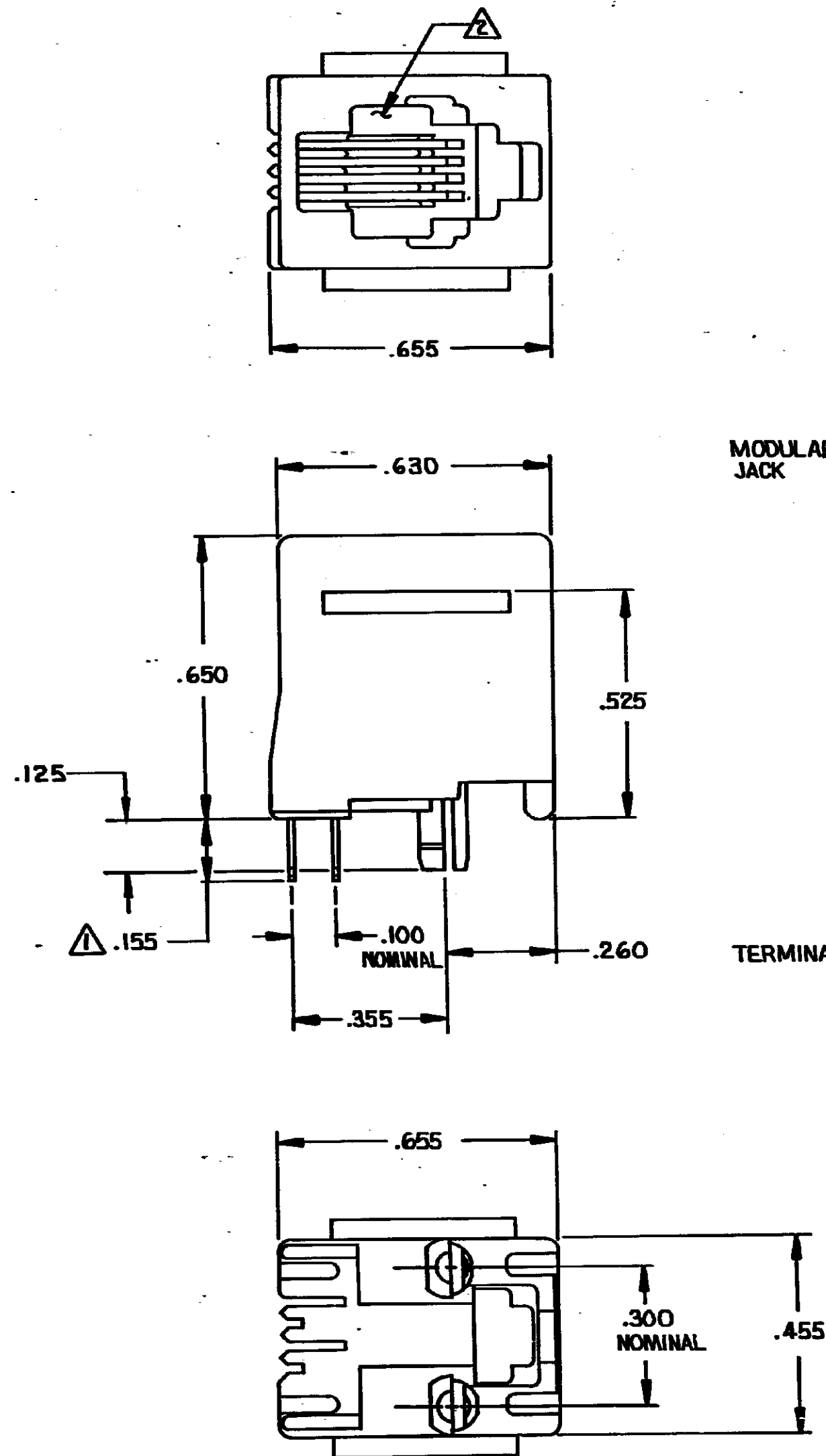


DRAWING MADE IN THIRD ANGLE PROJECTION

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LOC AA		DIST 22	
REVISIONS			
P	F	ZONE/LTR	DESCRIPTION
		L	REVISED; ECN AA-8120
DATE			APPROVED
3/25/84			LNS

D
C
B
A



- ⚠ MATERIAL: HOUSING PBT POLYESTER BLACK. TERMINAL-.0138 THICK PHOS-BRONZ PLATED WITH .00005 THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND .00008 THICK TIN-LEAD IN SOLDER AREA OVER .00005 THICK NICKEL UNDERPLATE.
- ⚠ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-.81 PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- 5. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- ⚠ BULK PACKAGED IN A TRAY.
- ⚠ PACKAGED 32 PER TUBE.

520257

⚠	-3
⚠	520257-2
PACKAGED	PART NO

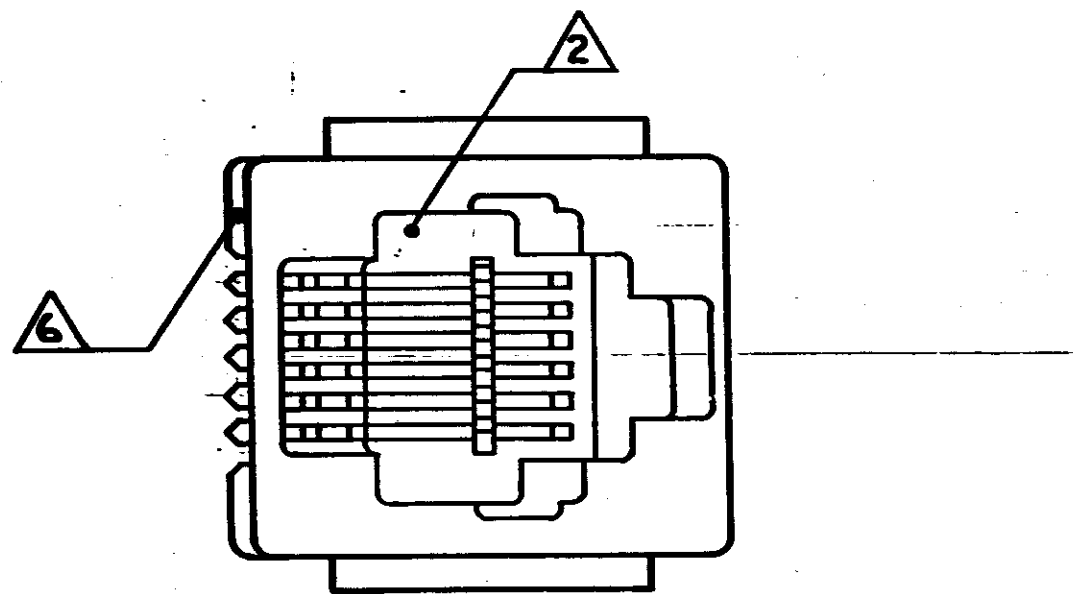
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ON: DECIMALS ± = ANGLES ± =	CONTRACT NO		AMP AMP INCORPORATED Harrisburg, Pa. 17105	
	DR	A. Bowen	8-29-84	NAME PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, TOP ENTRY, 4 POSITION, FLANGELESS, WITH PANEL STOPS
	CHK	B. Canty	8-30-84	
	MATERIAL	APPD	Joe A. Wilkerson	9/20/84
FINISH	DSGN APPD	OTHER APPD	APPD G. B. Wilkerson	9/20/84
	SIZE	C	FSCM NO	00779
	DRAWING NO	520257		
	SCALE	4:1		SHEET 1 OF 1

AMP 1471-7

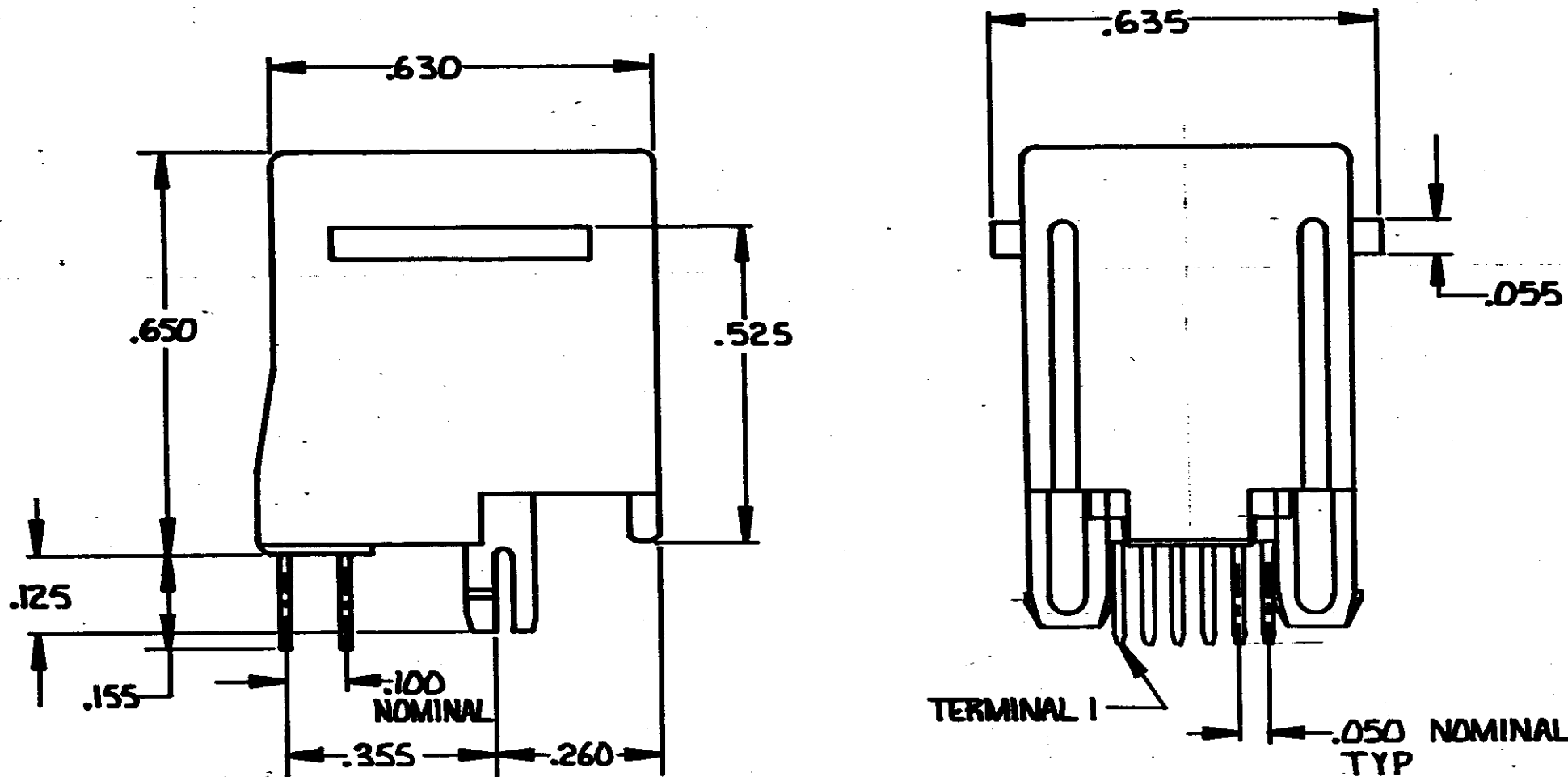
CUSTOMER DRAWING

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REVISIONS					
P	F	ZONE	DESCRIPTION	DATE	APPROVED
L		L	REVISED; ECN AA-6527	11-90	LHS NJ



- 1 MATERIAL: HOUSING - PBT POLYESTER, BLACK, TERMINAL - .0138 THICK PHOS-BRONZE PLATED WITH .00005 THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND .00008 THICK TIN-LEAD IN SOLDER AREA OVER .00005 THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- 5. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 6 VENDOR DESIGNATION SHALL BE THE LETTER 'A' ON THIS SURFACE.
- 7 BULK PACKAGED IN A TRAY.
- 8 PACKAGED 28 PER TUBE.



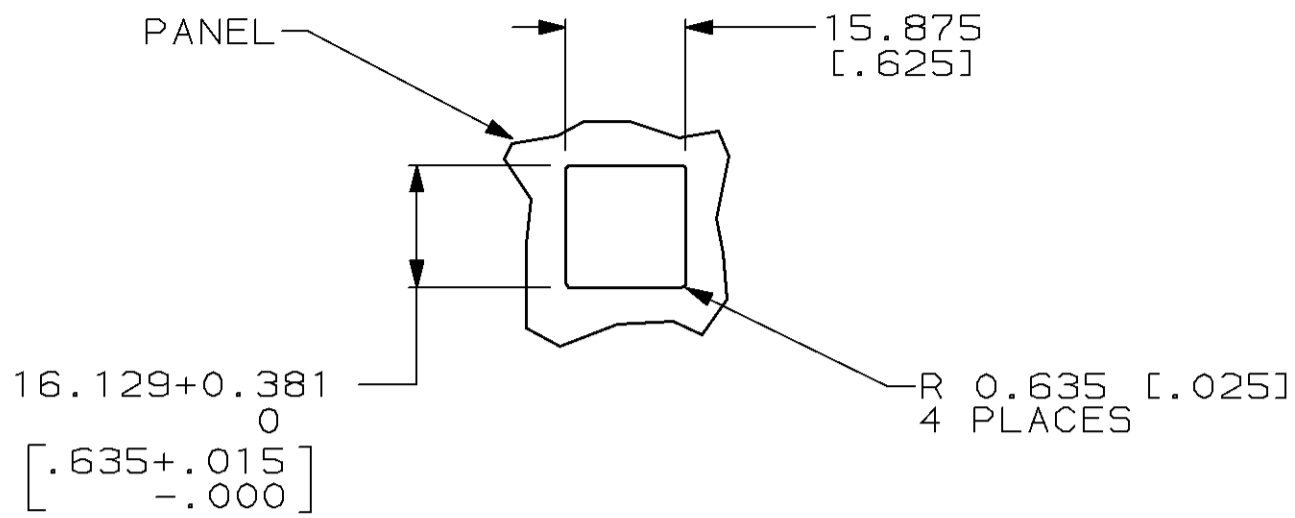
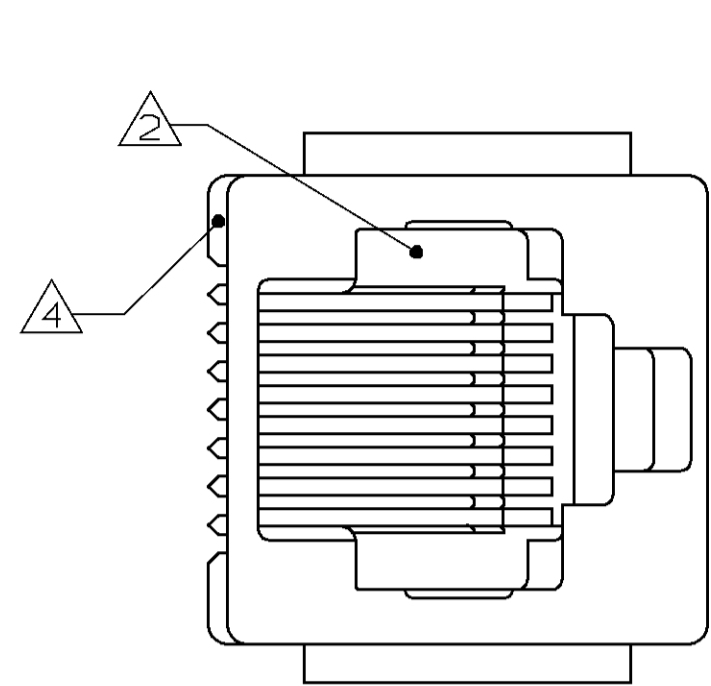
8	6	-4
7	6	-3
	4	520258-2
PACKAGED	CONTACTS	PART NO

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ON: DECIMALS ± ANGLES ±	CONTRACT NO	AMP INCORPORATED Harrisburg, Pa. 17105	
	DR <i>STWooten 12/2/87</i>	NAME PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, TOP ENTRY, 6 POSITION, FLANGELESS WITH PANEL STOPS	
MATERIAL	CHK <i>A.C. Clark 12-4-87</i>	SIZE	FSCM NO
FINISH	APPD <i>A.H. [Signature] 12/4/87</i>	C	00779
	APPD <i>A.B. [Signature] 12-4-87</i>	DRAWING NO	520258
	DGN APPD	SCALE 4:1	SHEET 1 of 1
	OTHER APPD		

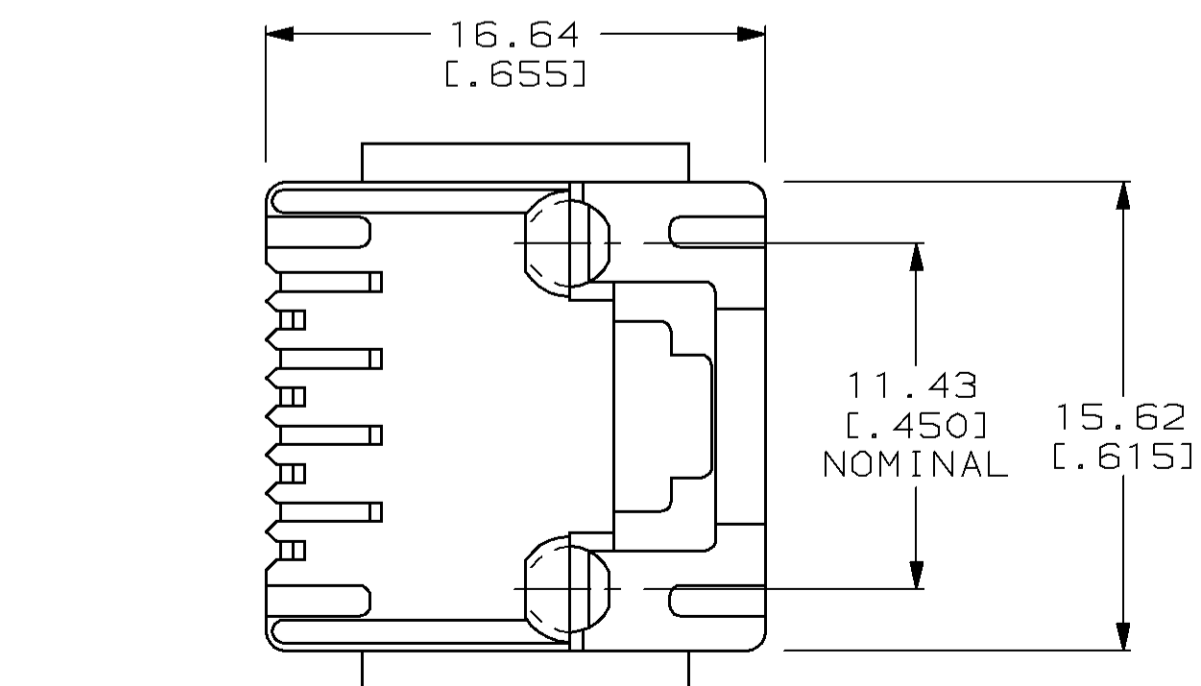
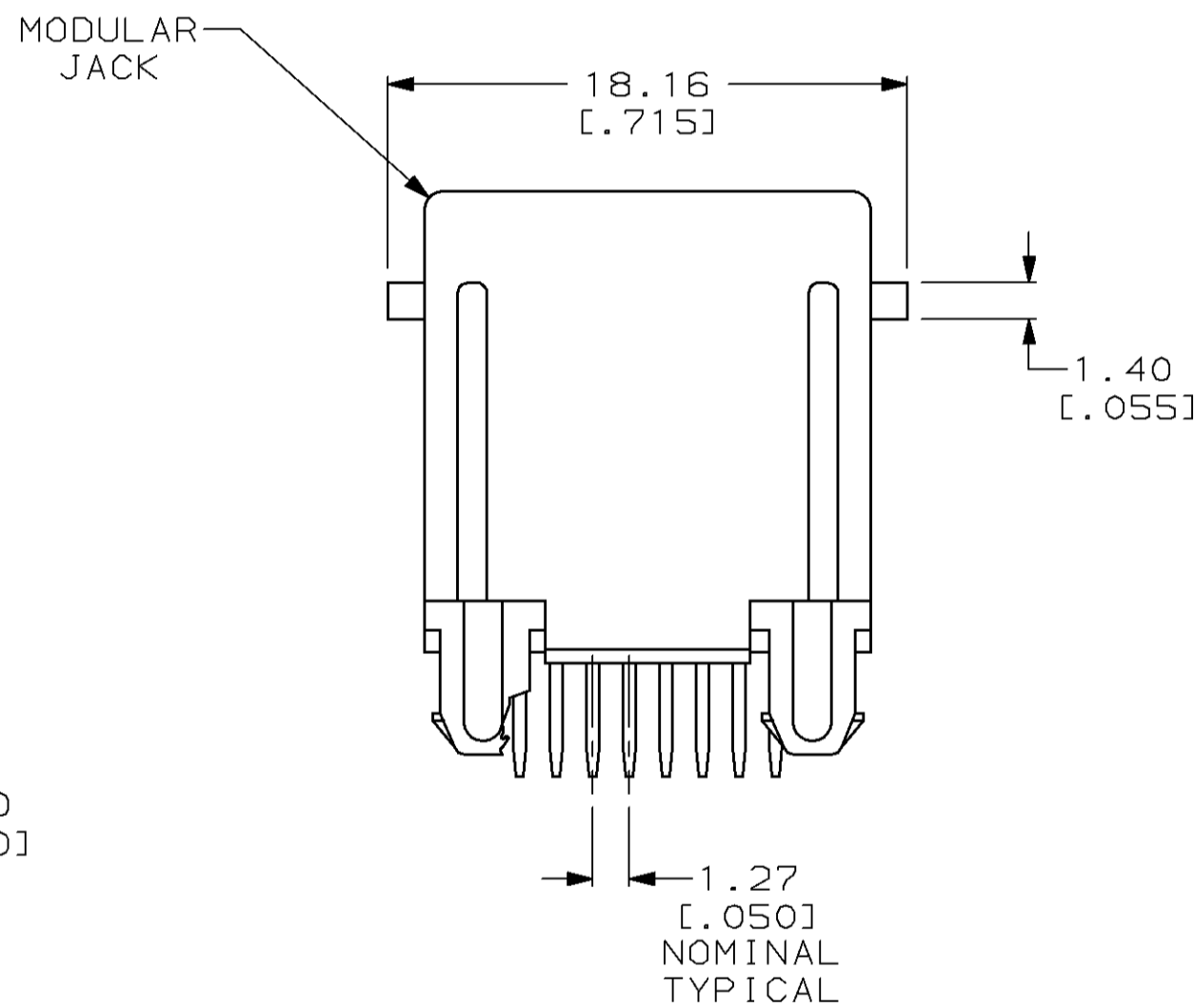
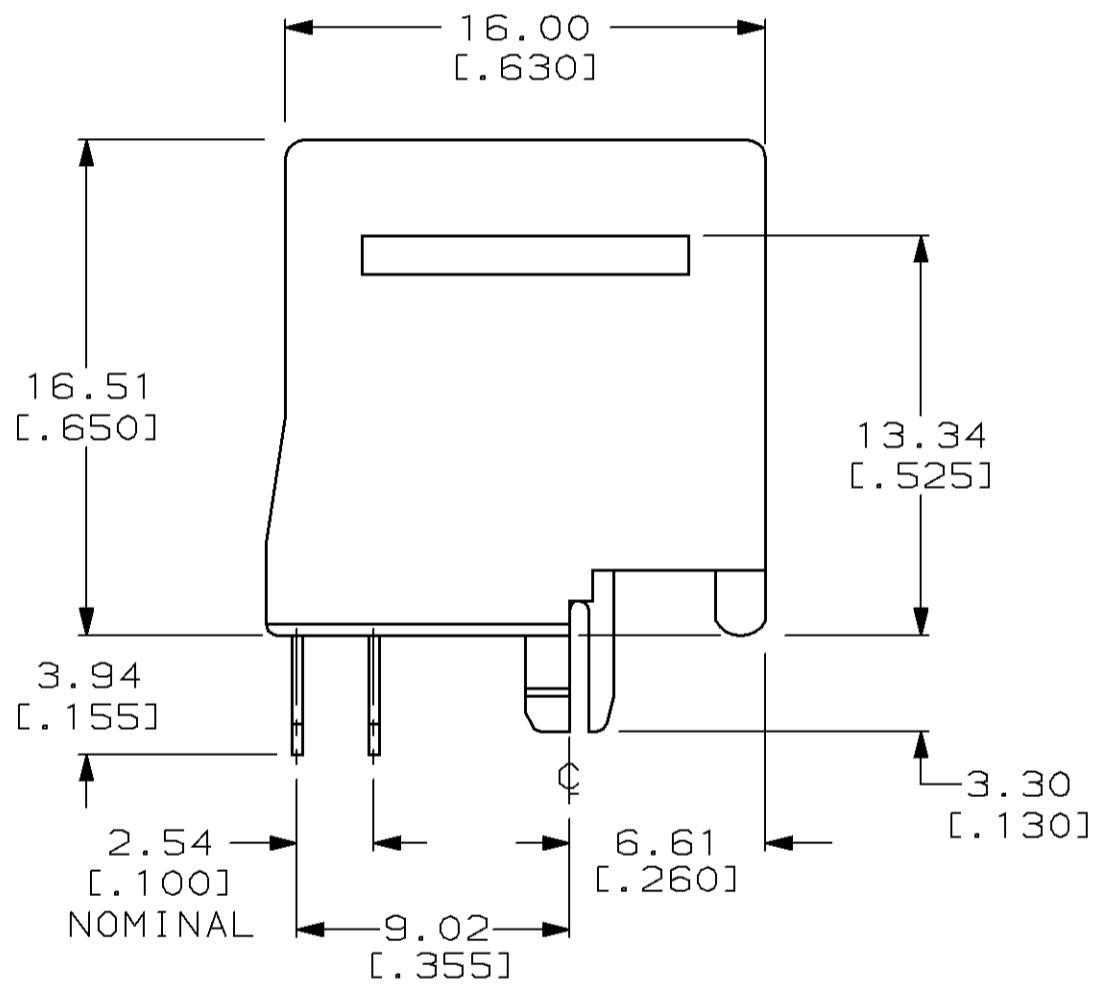
520258

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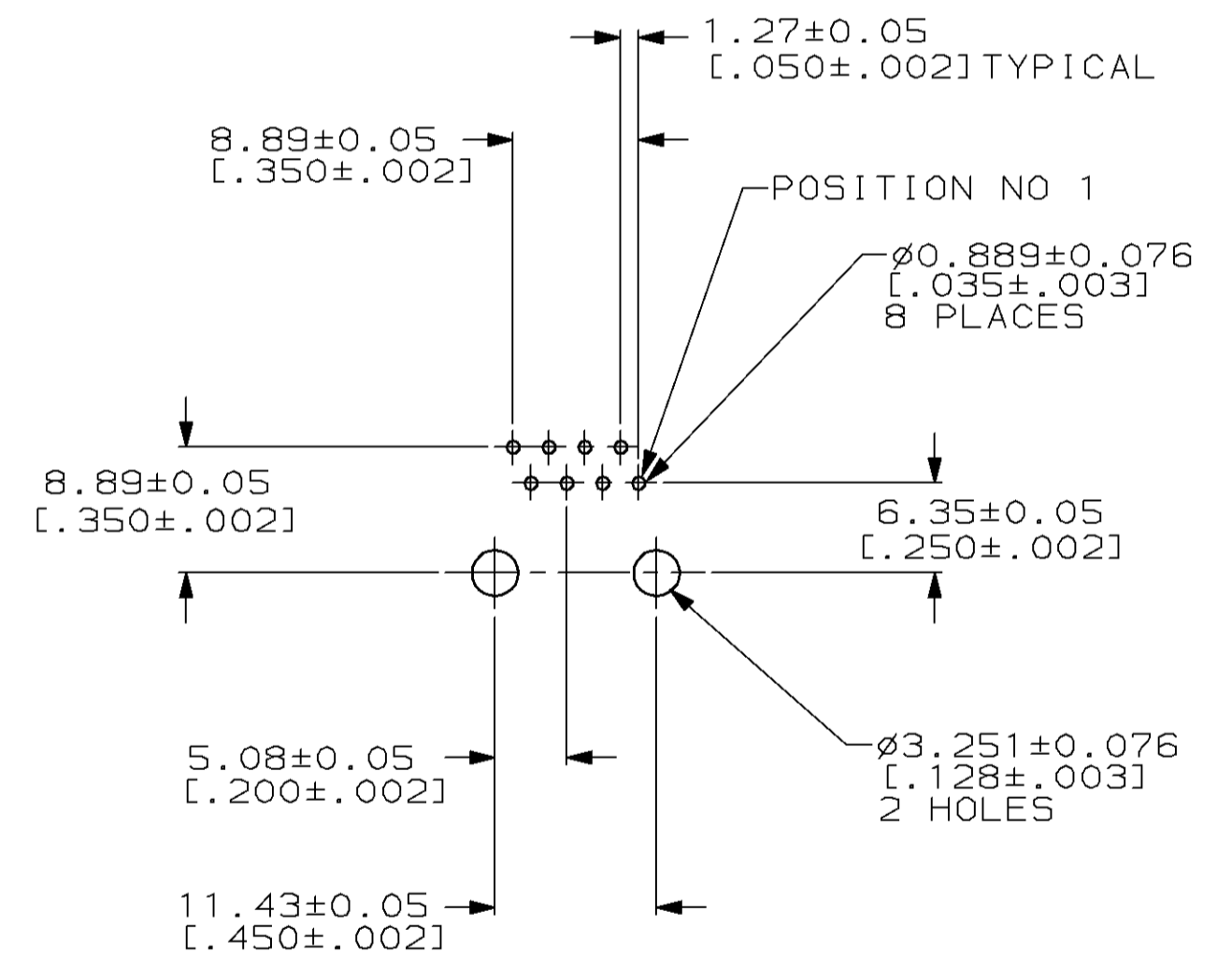
Loc		DIST		REVISIONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
AA	22	S	REV; EC 0502-0328-97	04JUN97	DS	DW	



PANEL CUTOUT
SCALE 1:1



- 1 MATERIAL: HOUSING- PBT POLYESTER, BLACK. TERMINAL- 0.35 [.0138] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03μm [.000080] THICK TIN-LEAD IN SOLDER AREA OVER 1.27μm [.000050] THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4 VENDOR DESIGNATION SHALL BE THE LETTER "A" ON THIS SURFACE.

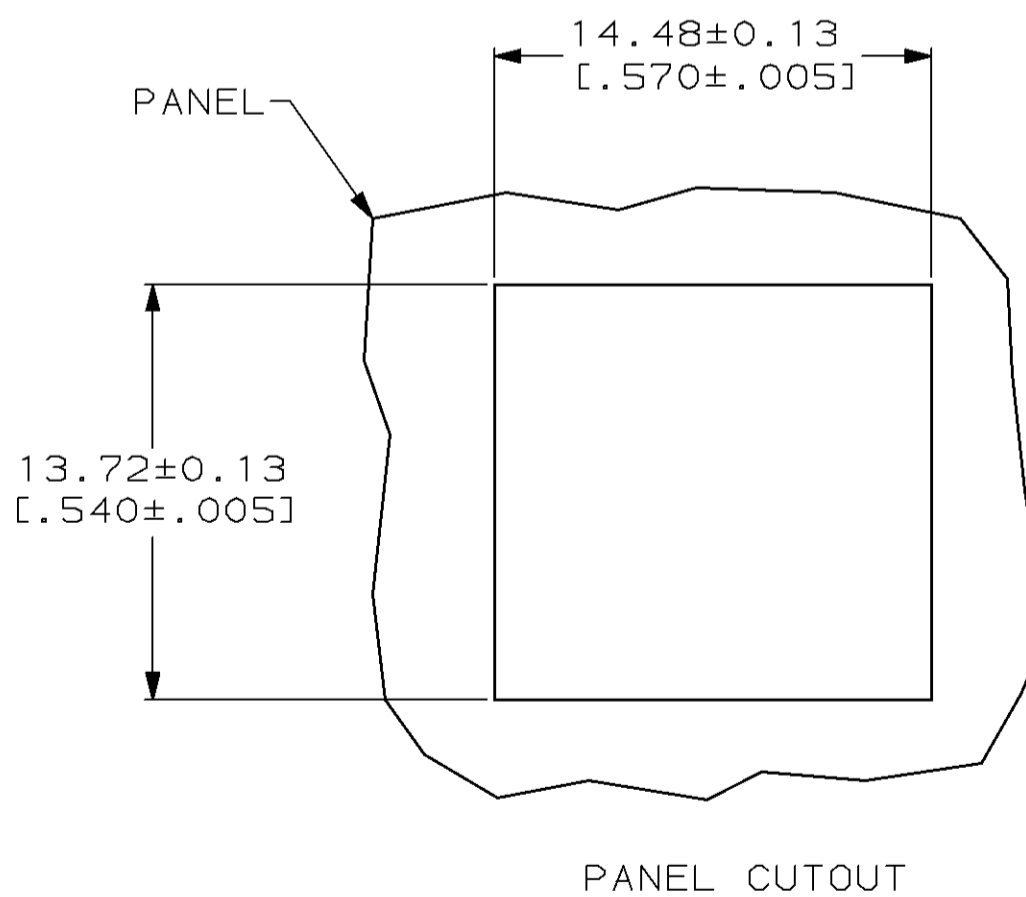
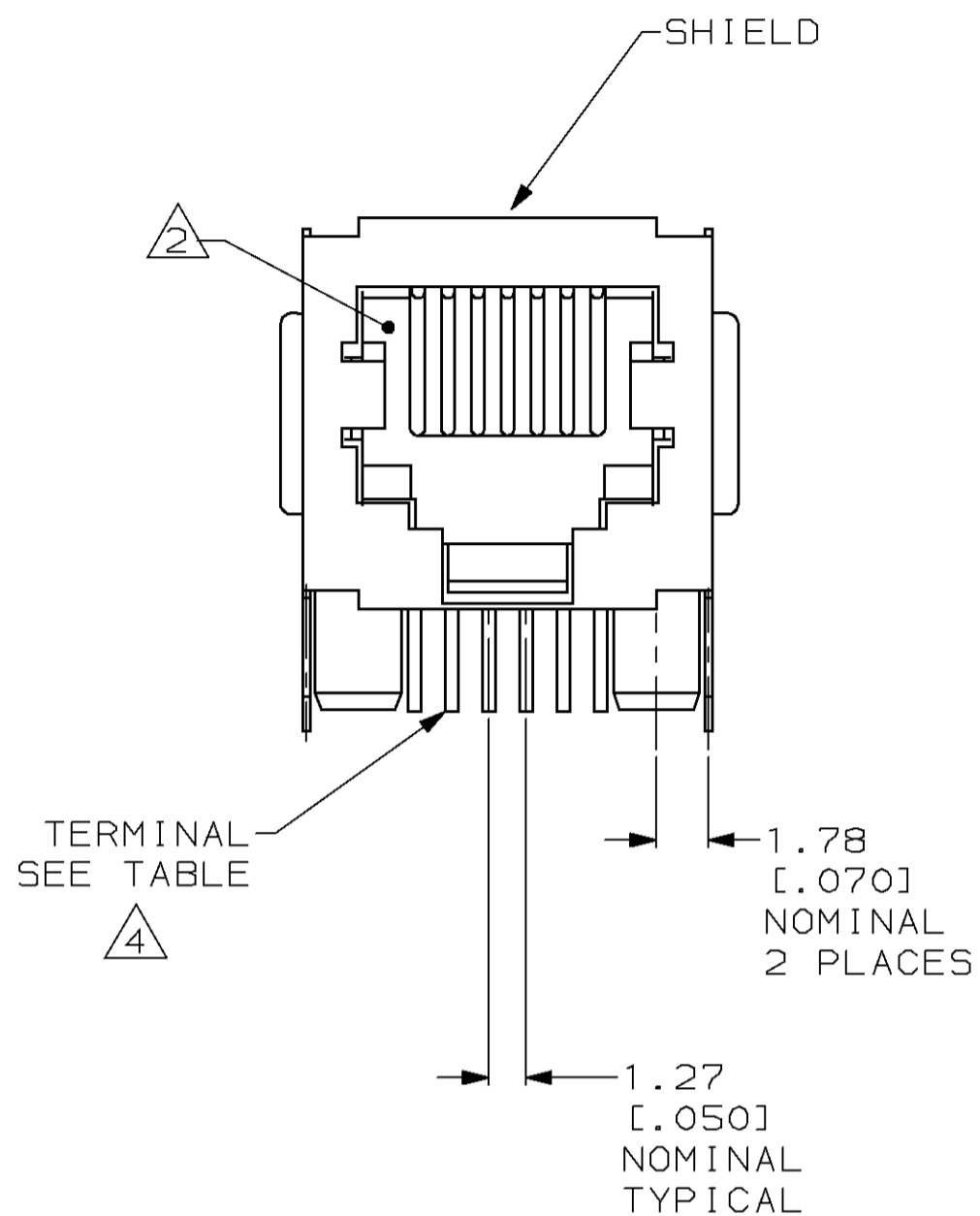
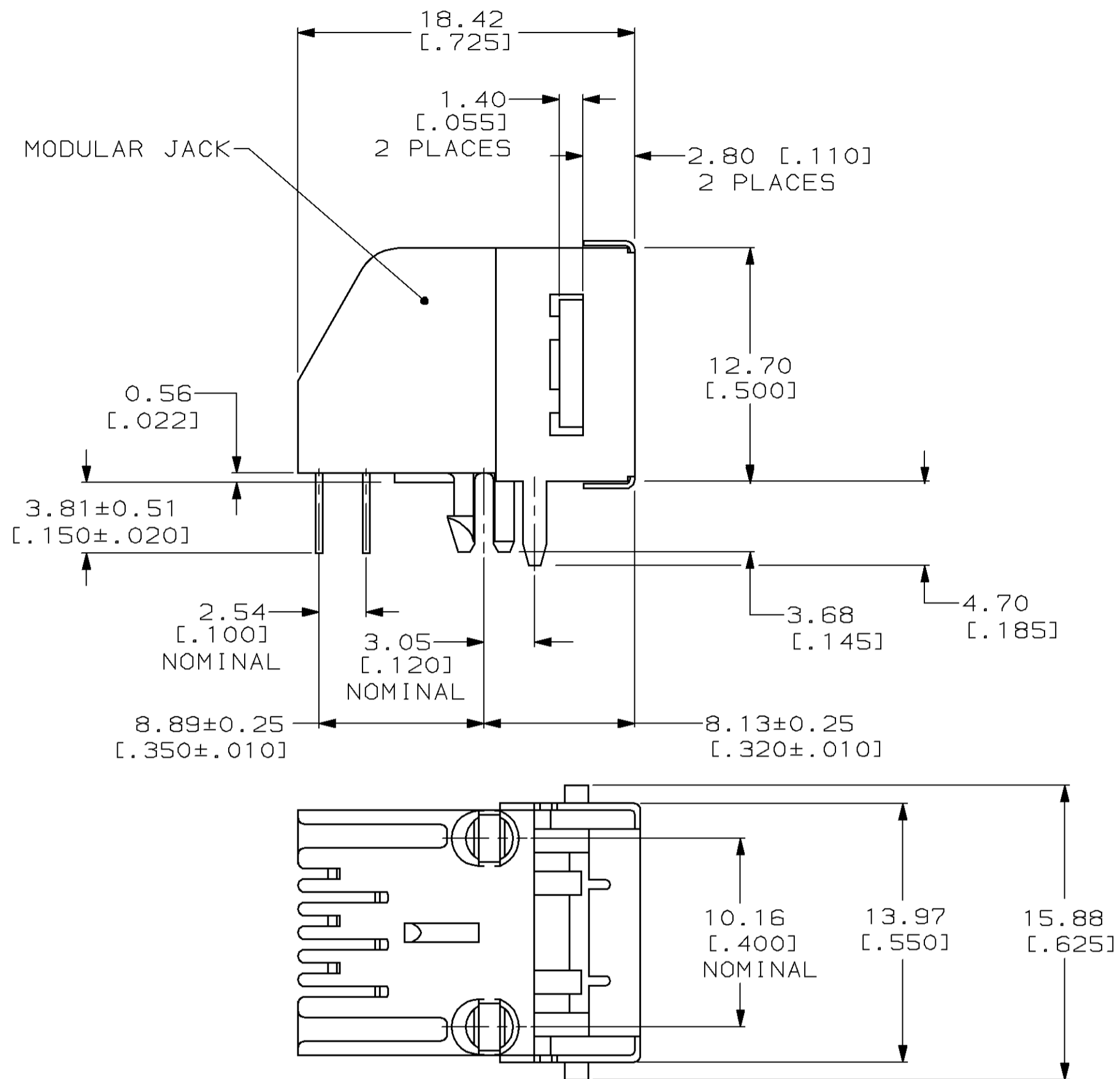


PRINTED CIRCUIT BOARD LAYOUT
NON-COMPONENT SIDE SHOWN
SCALE 2:1

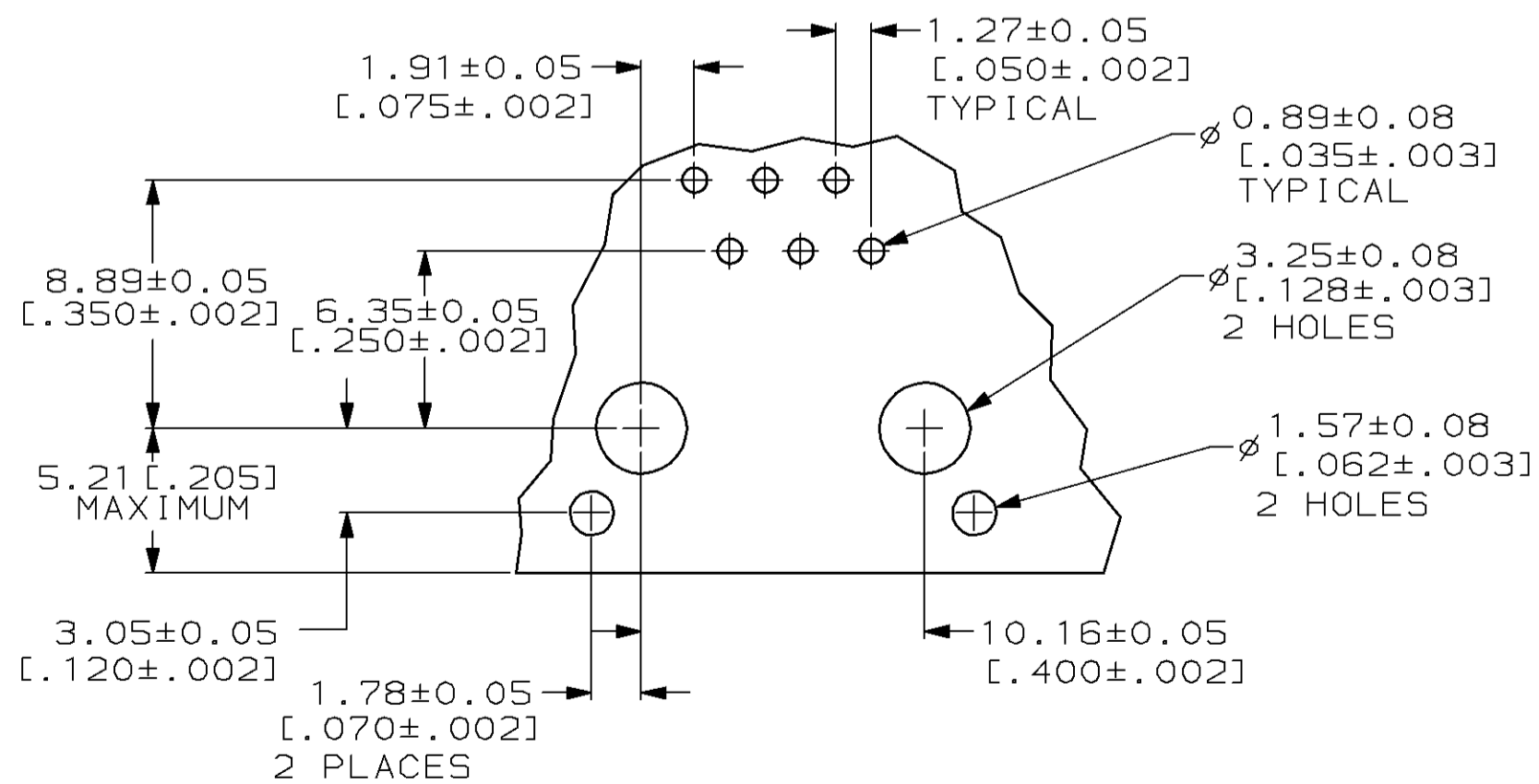
THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN L. MUSTAR/UTA 6-12-95	8	520259-4
DIMENSIONS: mm [inches]		CHK N. JONES 6-15-95	CONTACTS	PART NO
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±- 1 PLC ±- 2 PLC ±- 3 PLC ±- 4 PLC ±- ANGLES ±- FINISH ±-		APVD E. LAURER 6-22-95	AMP Incorporated Harrisburg, PA 17105-3608	
MATERIAL		NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, WITH PANEL STOPS	SIZE C	DRAWING NO 520259
1		PRODUCT SPEC 108-1163	CAGE CODE 00779	SCALE 4:1
		APPLICATION SPEC 114-2048	WEIGHT -	SHEET 1 OF 1
		CUSTOMER DRAWING	REV 5	

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LOC		DIST		REVISIONS			
P	LTR	DATE	DWN	APVD			
AA	22						
F		REV; EC 0502-0501-97	01AUG97	GG	DW		



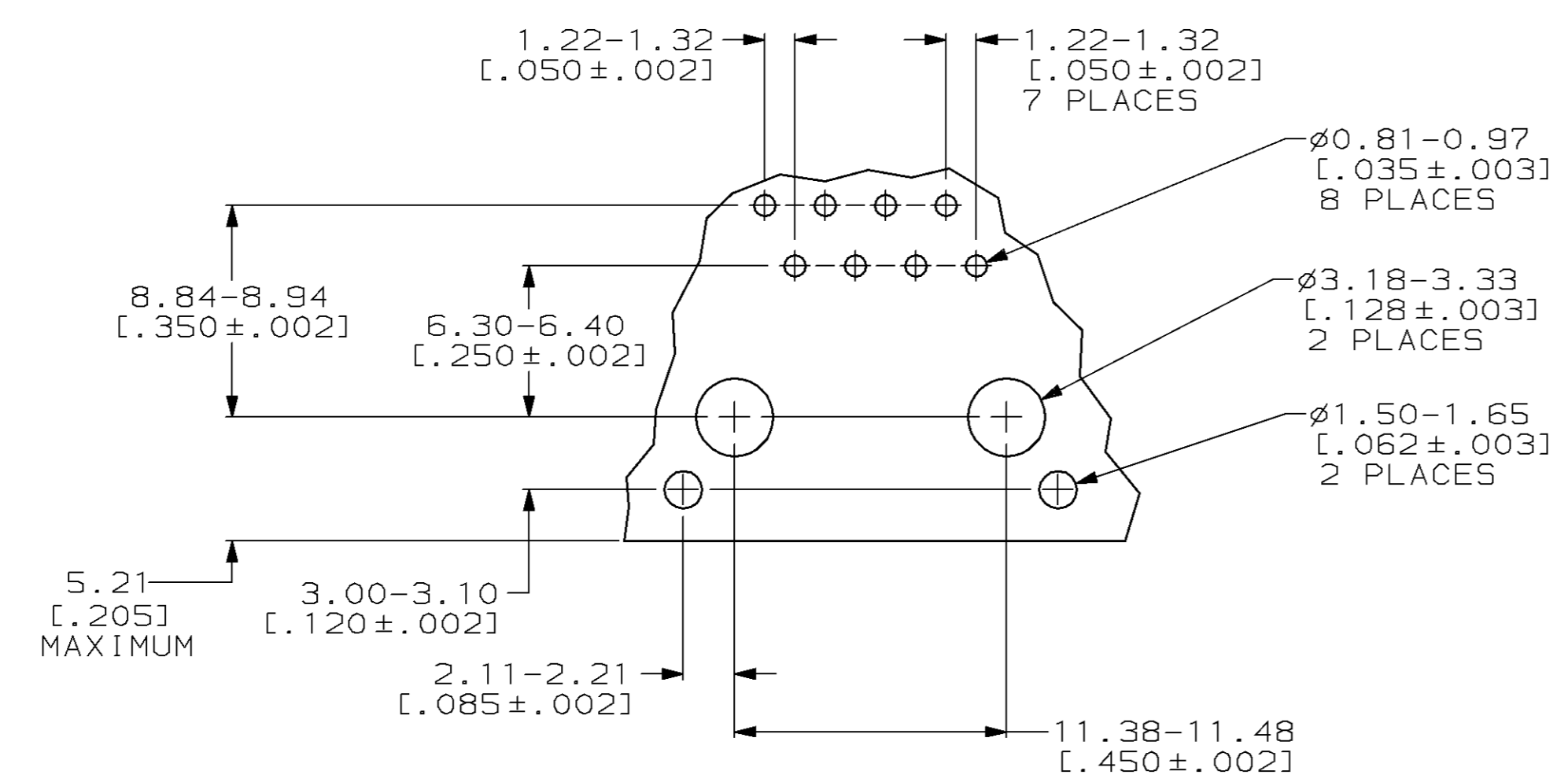
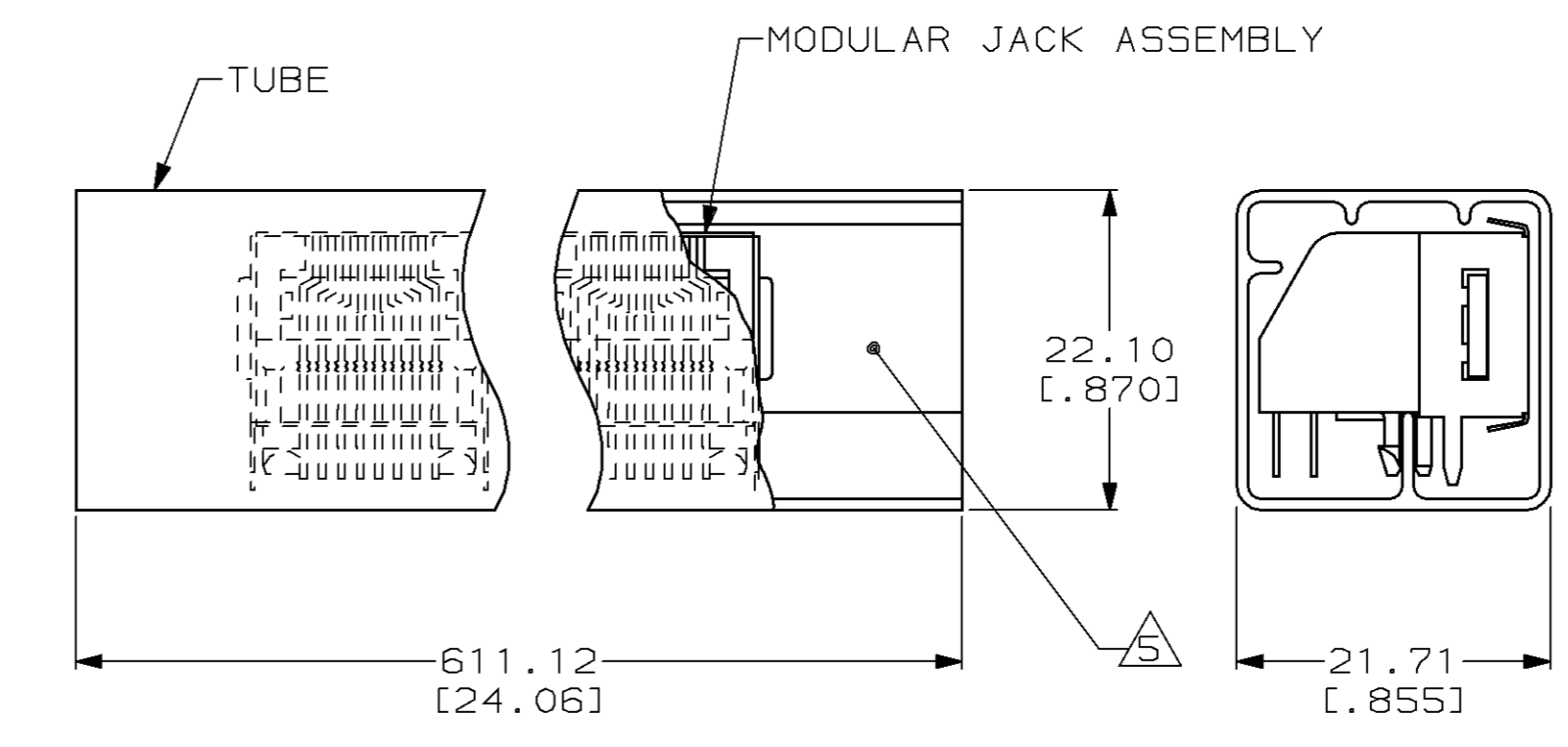
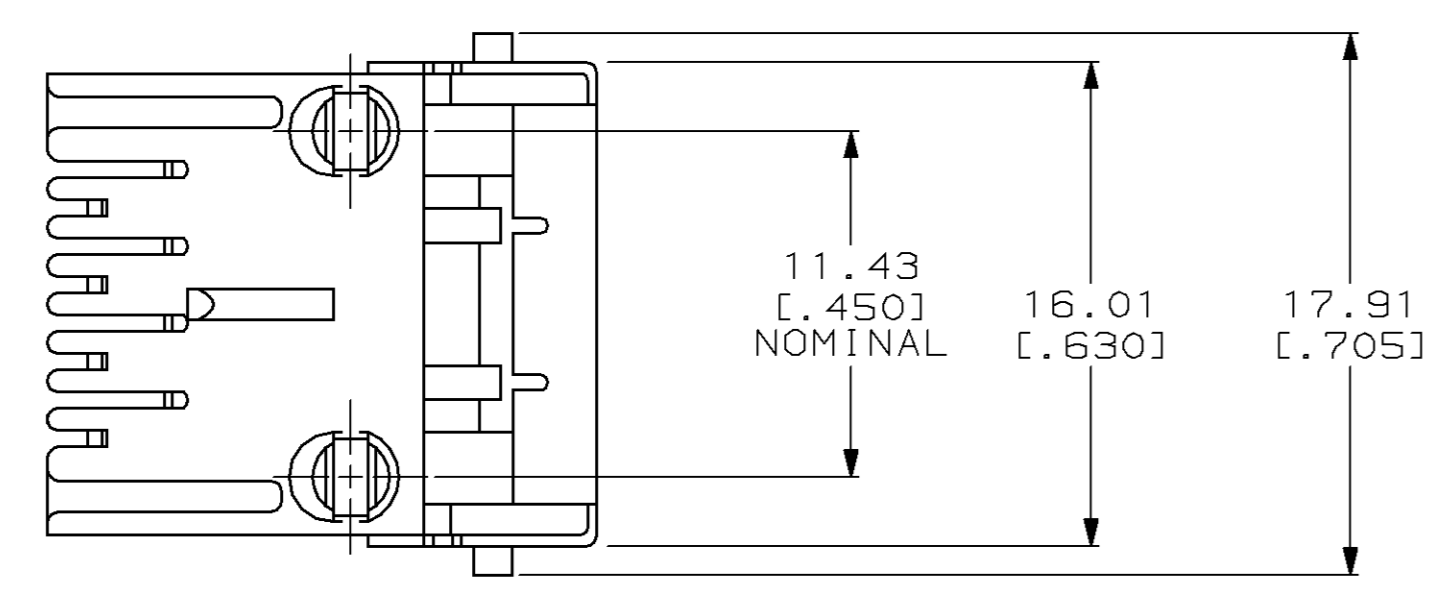
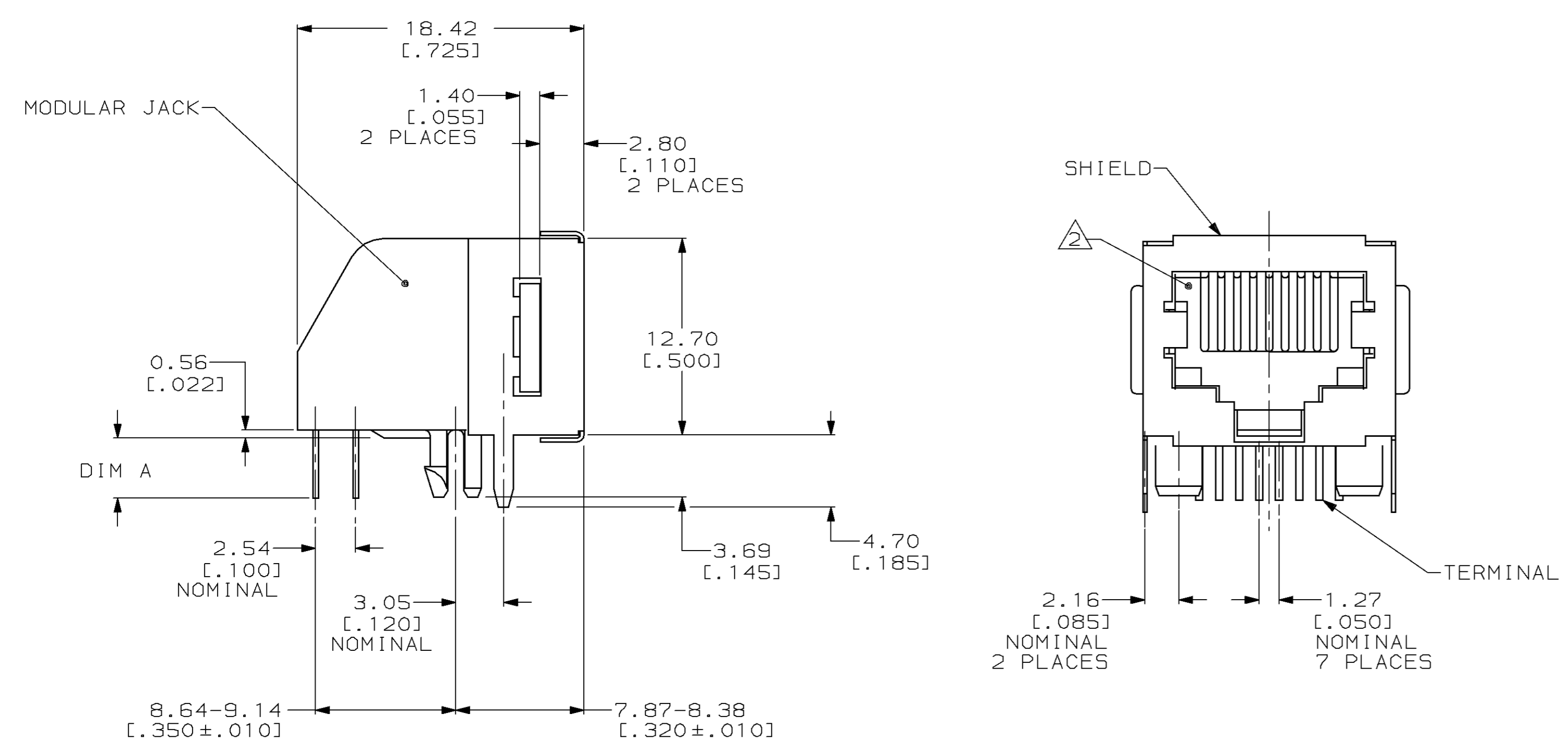
- 1 MATERIAL: HOUSING-PBT POLYESTER, BLACK. TERMINAL-.0138 THICK PHOS-BRONZE PLATED WITH .000050 THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND .000080 THICK TIN LEAD IN SOLDER AREA OVER .000050 THICK NICKEL UNDERPLATE SHIELD-.010 THICK COPPER ALLOY, TIN-LEAD PLATED.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4 TERMINALS FOR 555154-2 LOCATED IN CENTER POSITIONS.



4/4	555154-2
6	555154-1
TERMINALS REQUIRED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN G. GARRETT 7-13-95	AMP Incorporated Harrisburg, PA 17105-3608
		CHK N. JONES 8-25-95	
		APVD J. TONEY 9-1-95	NAME MODULAR JACK ASSEMBLY, SHIELDED, 6 POSITION, LOW PROFILE, RIGHT ANGLE, PRINTED CIRCUIT BOARD GROUND WITH PANEL STOPS
DIMENSIONS: mm (INCHES)		PRODUCT SPEC 108-1163	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPLICATION SPEC 114-2048	SIZE A2
0 PLC ±- 1 PLC ±- 2 PLC ±- 3 PLC ±- 4 PLC ±- ANGLES ±- FINISH ±-		WEIGHT -	CAGE CODE 00779
MATERIAL		CUSTOMER DRAWING	DRAWING NO C-555154
		SCALE 4:1	SHEET 1 OF 1
			REV F

LOC		DIST		P		ZONE		LTR		REVISIONS		DATE	APPD
AA	22									H	ADD: -6; NPR C96-63 & EC 0210-0227-96	25MAR96	GG DA



SUGGESTED PRINTED CIRCUIT BOARD
 MOUNTING HOLE LAYOUT
 VIEW SHOWN IS CIRCUIT SIDE OF BOARD

- 1 MATERIAL:
 HOUSING-PBT POLYESTER BLACK.
 TERMINAL-0.36[0.014] THICK PHOS-BRONZE PLATED WITH 1.27µm[0.00050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm[0.00080] THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm[0.00050] THICK NICKEL UNDERPLATE.
 SHIELD-0.25[0.010] THICK COPPER ALLOY, TIN-LEAD PLATED.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3 DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4 BULK PACKAGED IN A TRAY.
- 5 32 ASSEMBLIES PACKAGED PER TUBE, SEE DETAIL B.

DIM A	PACKAGED	PART NO
1.78-2.79 [0.09±0.02]	4	555153-6
2.54-3.05 [0.11±0.01]	4	555153-5
4.06-4.57 [0.17±0.01]	5	555153-4
3.30-4.32 [0.15±0.02]	5	555153-3
	4	555153-1

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES]		DR 5-20-94 J. GALLUCCI/UTA		AMP AMP Incorporated Harrisburg, PA 17105-3608	
TOLERANCES ON:		CHK 5-24-94 D. HUSSEY			
2 PLC DEC ±		APPD 5-25-94 J. TONEY		NAME MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, LOW PROFILE, RIGHT ANGLE WITH PRINTED CIRCUIT BOARD GROUND AND PANEL STOPS	
3 PLC DEC ±		APPD 5-25-94 H. McGRATH			
ANGLES ±		PRODUCT SPEC 108-1163		SIZE D	
FINISH		APPLICATION SPEC 114-2048		CAGE CODE 00779	
MATERIAL		WEIGHT -		DRAWING NO C-555153	
SCALE 4:1		SHEET 1 OF 1		CUSTOMER DRAWING	

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NOTE

All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters [and inches]. Unless otherwise specified, dimensions have a tolerance of ± 0.13 [.005] and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of AMP* Modular Jacks designed to be mounted to a printed circuit (pc) board. The jacks are available as unshielded, shielded, and filtered designs to accommodate specific application requirements. There are 4 position handset jacks and there are 4, 6, 8, and 10 position line jacks. This specification pertains to all shielded and unshielded jacks with top and side entry ports, and with single or multiple ports.

When corresponding with AMP personnel, use the terminology provided on this specification to help facilitate assistance. Basic terms and features of components are provided in Figure 1.

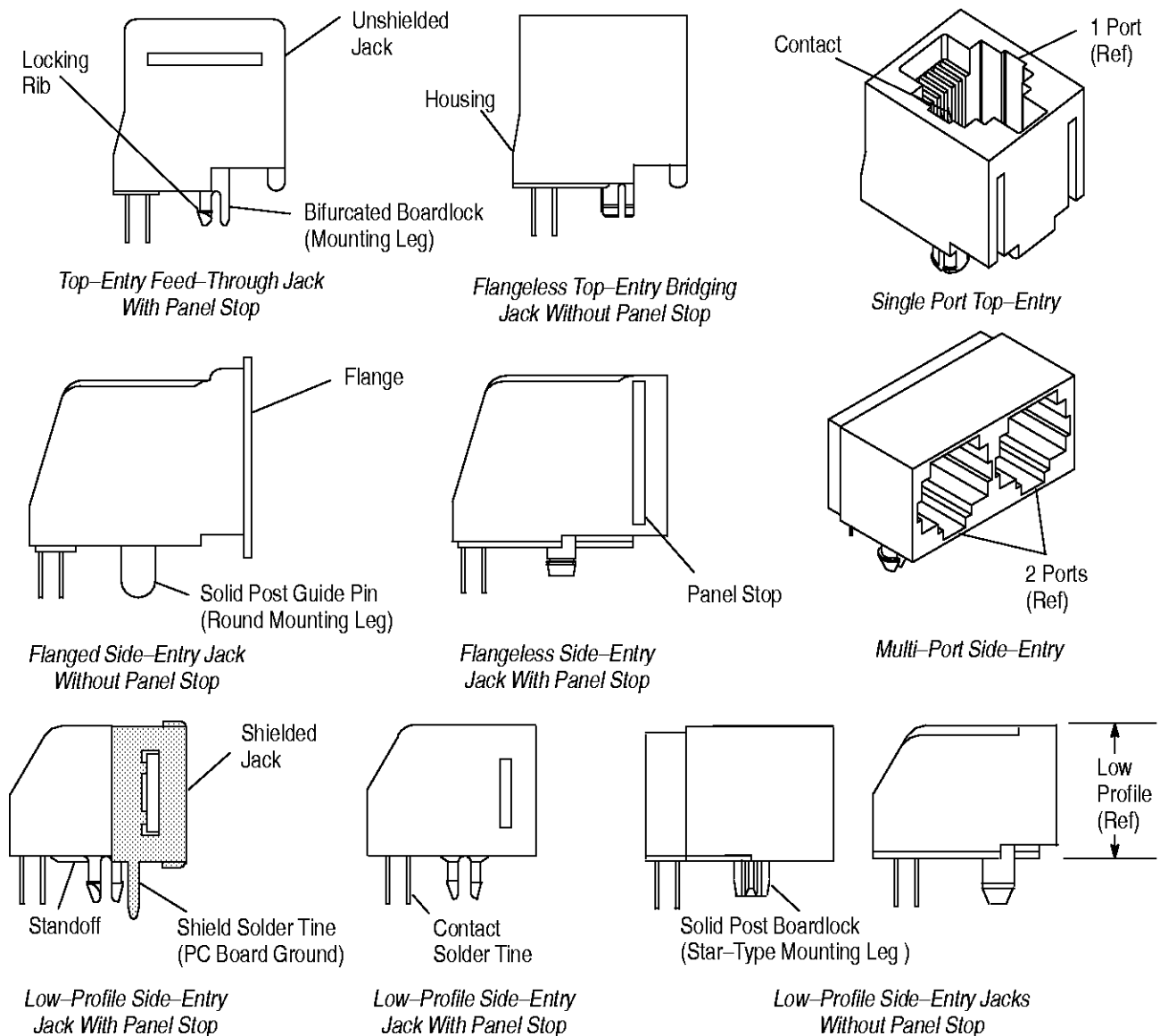
**Typical Modular Jack Designs**

Figure 1

2. REFERENCE MATERIAL**2.1. Revision Summary**

This paragraph is dedicated to a revision summary of changes and additions since the previous release of this application specification. The following changes were made for this revision (Rev M).

Per EC 0990-1094-97:

- Replaced pc board layout of unshielded 6 position jacks
- Replaced pc board layout of shielded 6 position jacks
- Replaced pc board layout of shielded 8 position top entry jack
- Added pc board layout for unshielded 10 position jacks
- Added pc board layout for shielded 10 position jacks
- Changed some text and layouts for terminology consistency and clarity

2.2. Customer Assistance

Reference Part Number 520250 and Product Code 1055 identify the pc board mounted modular jacks. These numbers are used in the AMP network of customer service to access tooling and product application information. This service is provided by your local AMP Representative (Field Sales Engineer, Field Applications Engineer, etc) or, after purchase, by calling the Tooling Assistance Center or AMP FAX/Product information number at the bottom of page 1.

2.3. Drawings

AMP Customer Drawings for product numbers are available from the service network. The information on the customer drawing and this specification takes priority over any other document supplied by AMP Incorporated. If there is a conflict with the information on the customer drawing and this specification call either of the customer service numbers at the bottom of page 1 for assistance.

2.4. Product Specifications

AMP Product Specifications 108-1163 (shielded and unshielded modular jacks), 108-1721 (unshielded bridging jacks), and 108-1432 (filtered modular jacks) cover test and performance requirements.

2.5. Instructional Material

AMP Corporate Bulletin No. 401-52 is available from the service network. This bulletin provides information on various flux types and characteristics along with the commercial designation and flux removal procedures. A checklist is attached to the bulletin as required for information on soldering problems.

3. REQUIREMENTS**3.1. Storage****A. Ultraviolet Light**

Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the modular jack housings.

B. Shelf Life

Modular jacks should remain in the shipping containers until ready for use to prevent damage. The products should be used on a first in, first out basis to avoid storage contamination that could adversely affect signal transmissions.

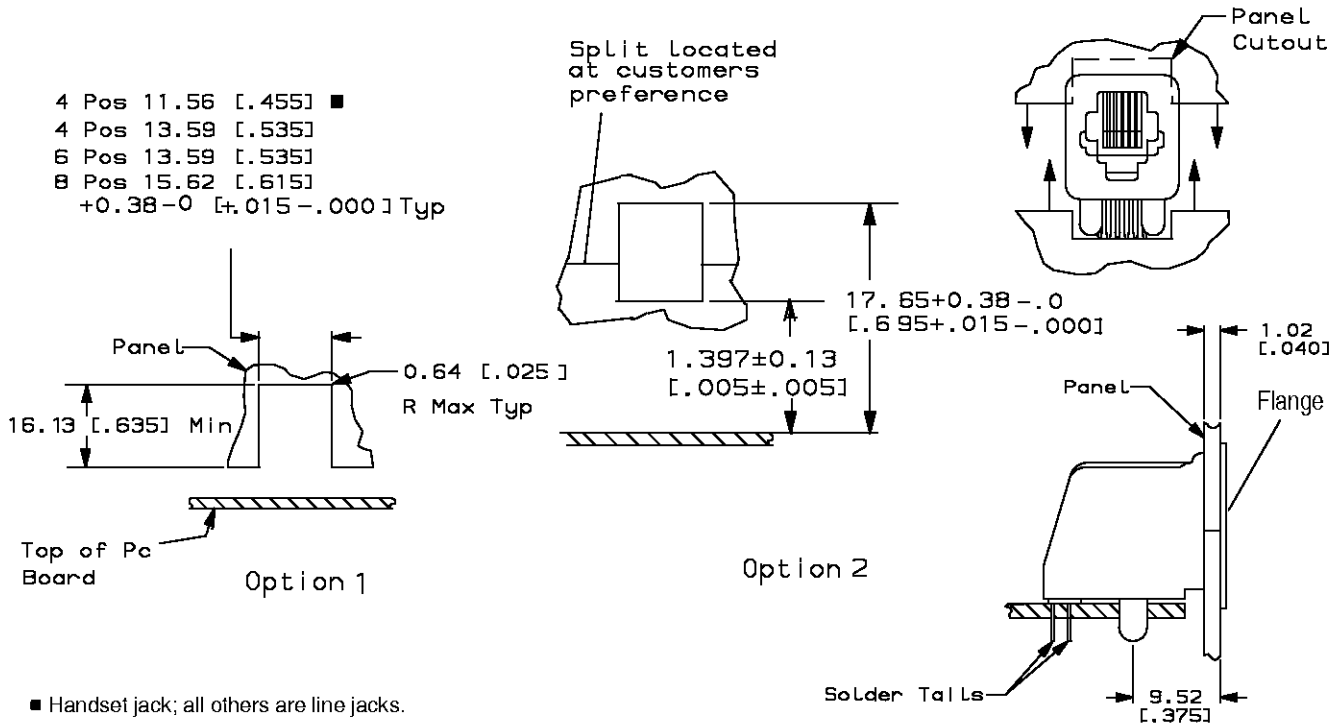
C. Chemical Exposure

Do not store modular jacks near any chemicals listed below, as they may cause stress corrosion cracking in the components.

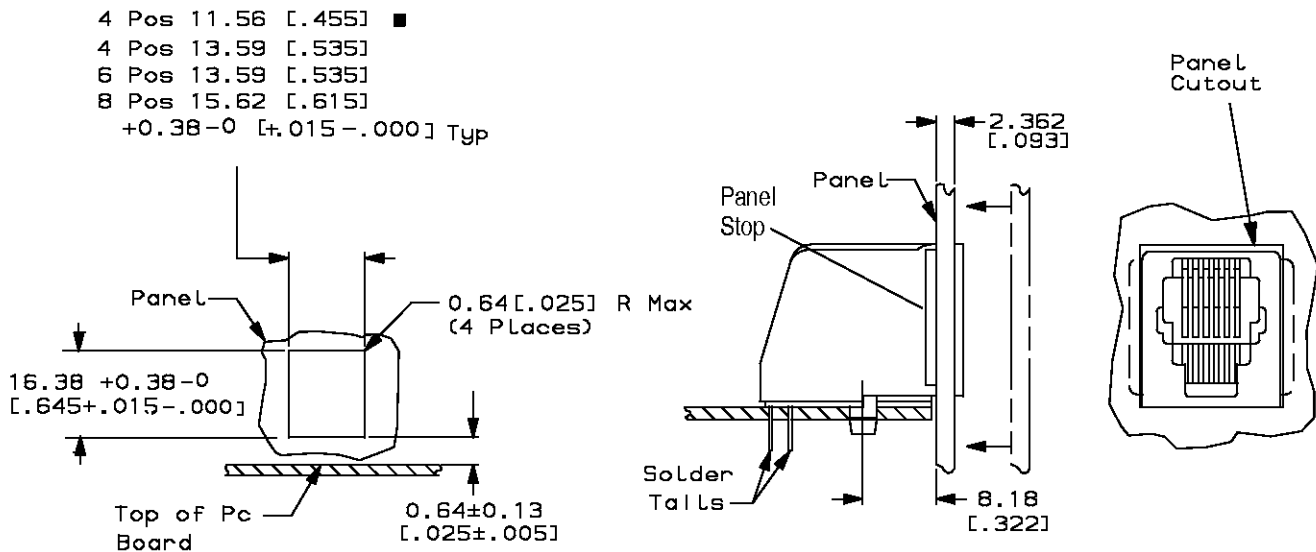
Alkalies	Ammonia	Cittrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates

3.2. Panel Cutout

The flanged jacks will require a panel cutout that will allow the jack flange to be on the outside of the panel. This may be accomplished with three-sided panel cutout (Option 1) or a split panel cutout (Option 2). The flangeless jacks with panel stops are designed to be back mounted to a panel connected on all four sides. The suggested panel cutout for each style of modular jack is provided in Figure 2.



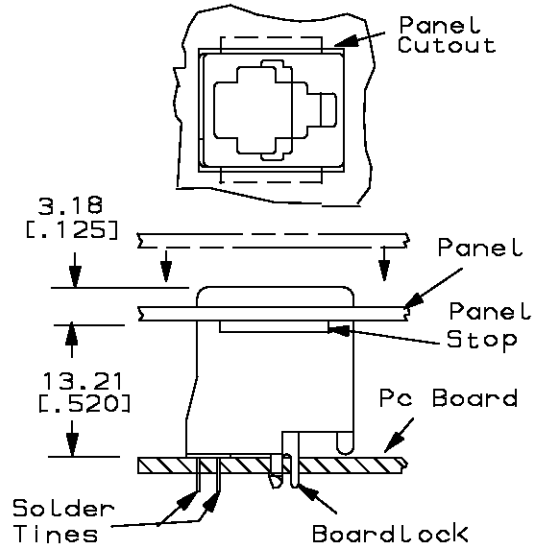
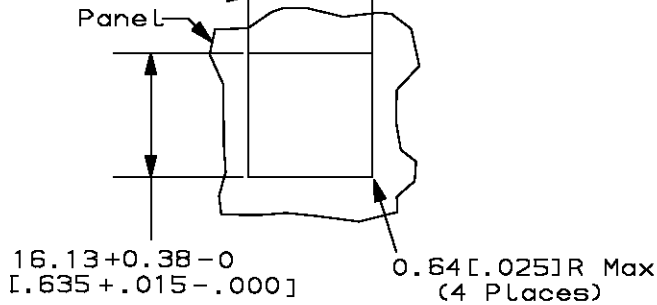
Unshielded 4 Position Handset, and 4, 6, and 8 Position Line Side-Entry Jacks with Flange



Unshielded 4 Position Handset, and 4, 6, and 8 Position Line Flangeless Side-Entry Jacks with Panel Stop

Figure 2 (cont'd)

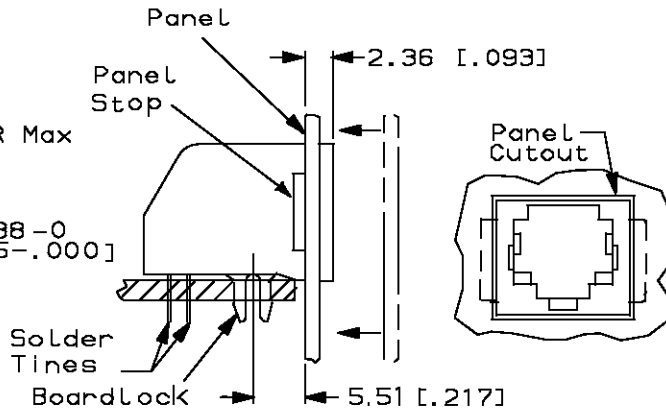
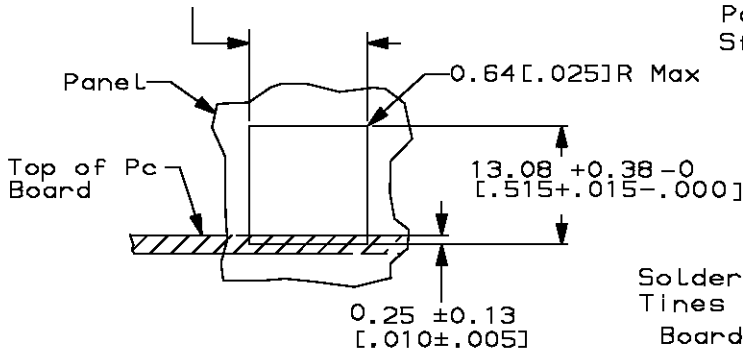
- 4 Pos 11.81 [.465] ■
- 4 Pos 13.84 [.545]
- 6 Pos 13.84 [.545]
- 8 Pos 15.88 [.625]
- +0.38 - 0 [+ .015 - .000] Typ



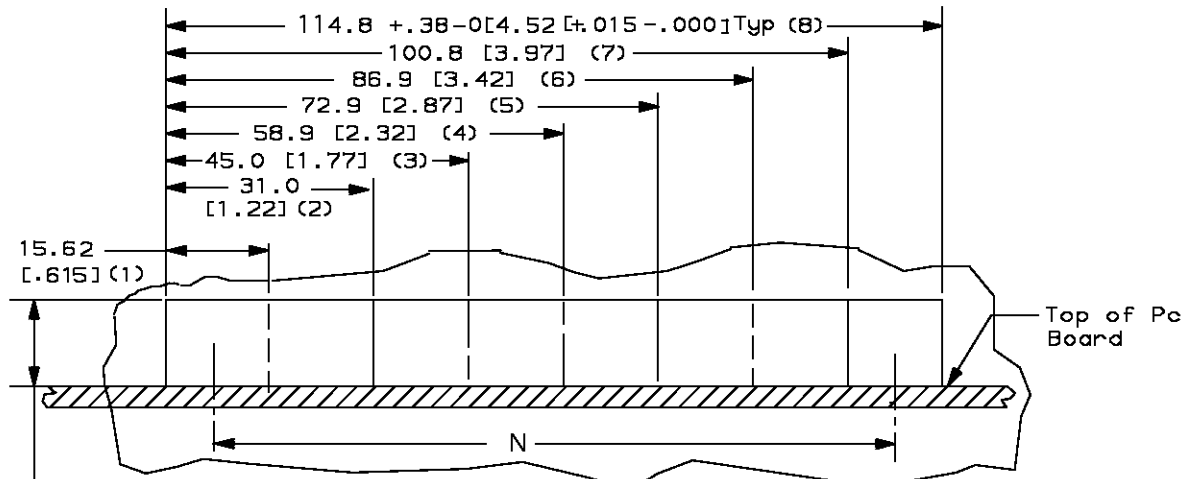
■ Handset jack; all others are line jacks.

Unshielded 4 Position Handset, and 4, 6, and 8 Position Line Top-Entry Jacks

- 4 Pos 13.60 [.535]
- 6 Pos 13.60 [.535]
- 8 Pos 15.62 [.615]
- +0.38 - 0 [+ .015 - .000] Typ



Unshielded 4, 6, and 8 Position Line Low-Profile Side-Entry Jacks

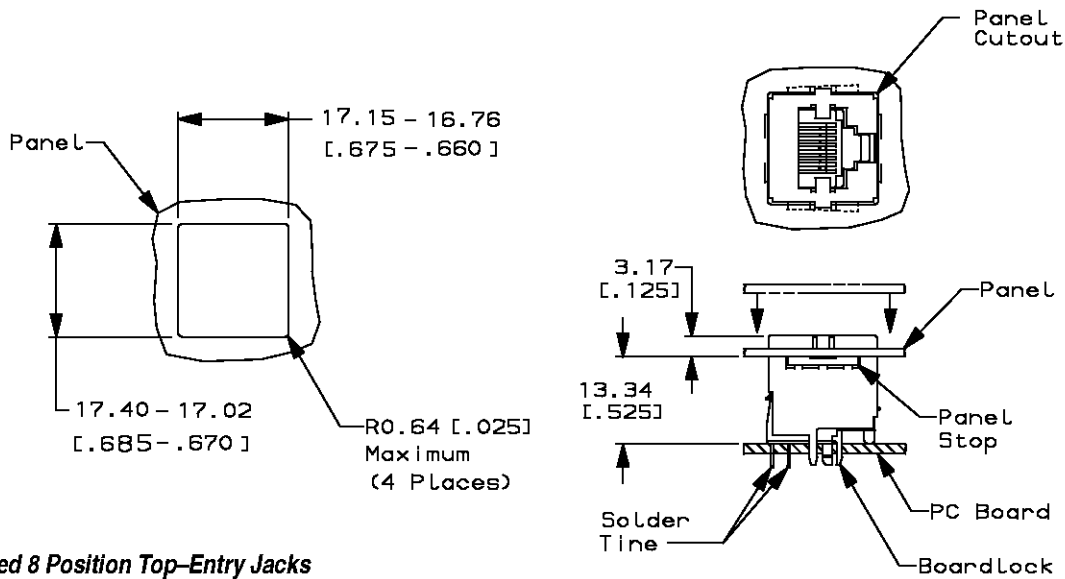


13.84 + 0.38 - 0 [.545 + .015 - .000]

Unshielded 8 Position Multi-Port Jacks

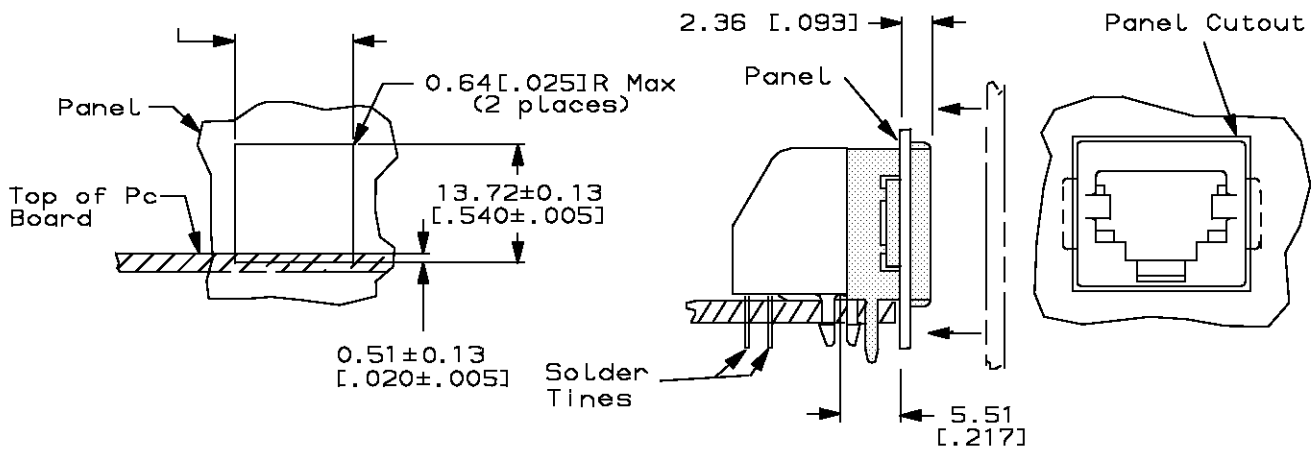
Figure 2 (cont'd)

(Number in parenthesis) = Number of Ports

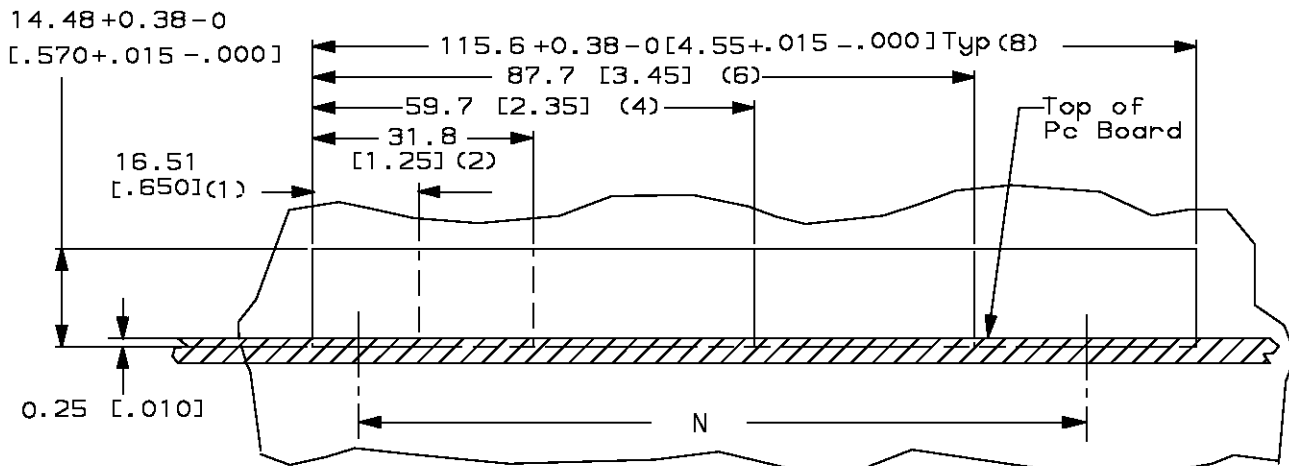


Shielded 8 Position Top-Entry Jacks

6 Pos 14.22 [.560]
 8 Pos 16.26 [.640] +0.38 - 0 [+ .015 - .000] Typ



Shielded 6 and 8 Position Side-Entry Low-Profile Jacks



Shielded 8 Position Multi-Port Modular Jacks

(Number in parenthesis) = Number of Ports

Figure 2 (end)

3.3. PC Board Layout

The solder time hole layout for all 4, 6, and 8 position single-port jacks is typical for all jacks with comparable positions, and each port of a multi-port jack is identical to the hole pattern for comparable single-port jacks. The mounting hole location will depend of the number of ports and contact positions. The pc board layout views shown represent the **component side** of the pc board.

NOTE Mounting holes in pc board should be made with 3.25 [.128 (No. 30)] drill. Do NOT use a 3.18 [.125 (1/8)] drill bit.

A. Unshielded Jacks

The hole patterns that apply to all unshielded side-entry and top-entry jacks are provided in Figure 3.

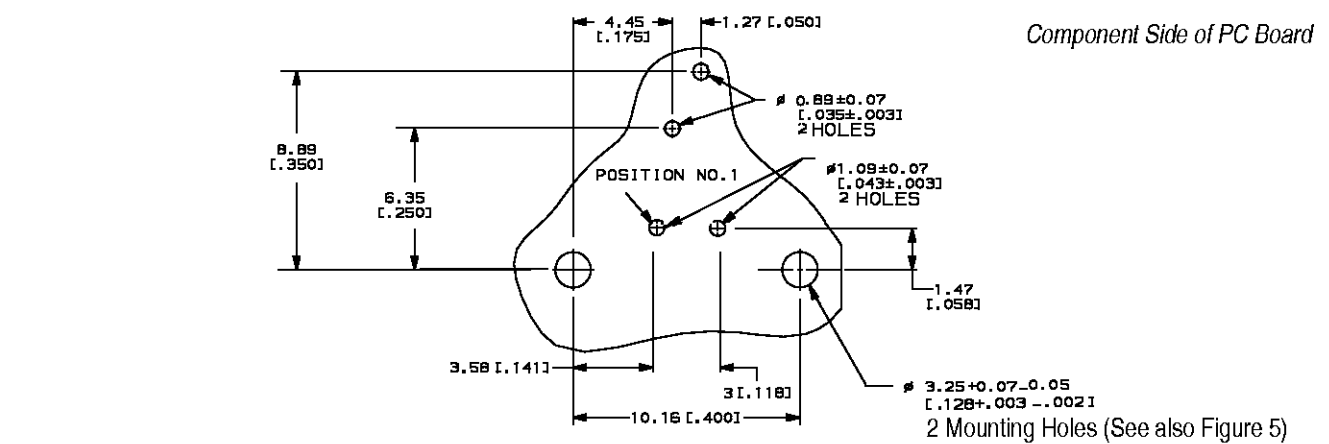
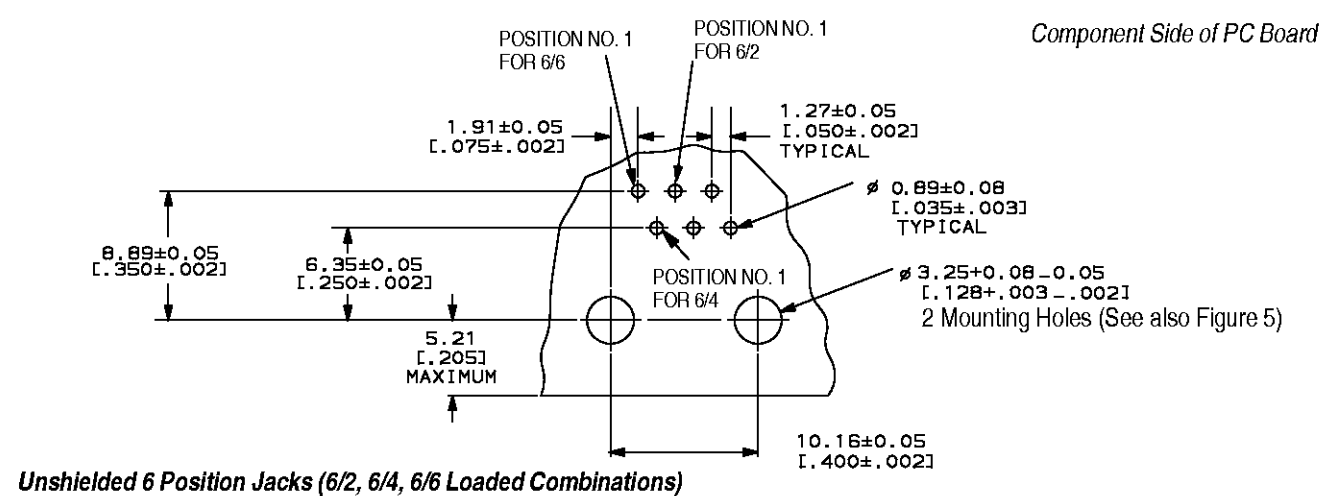
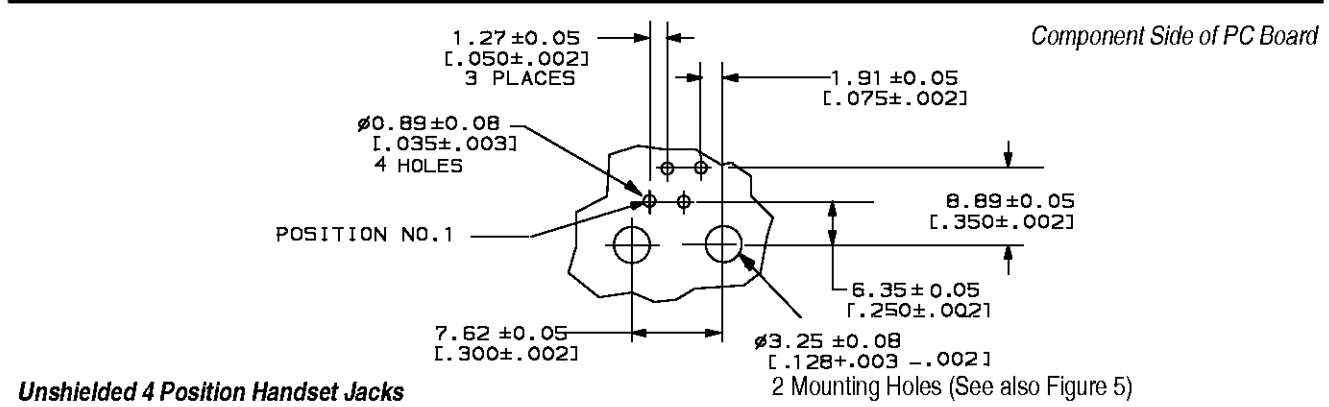
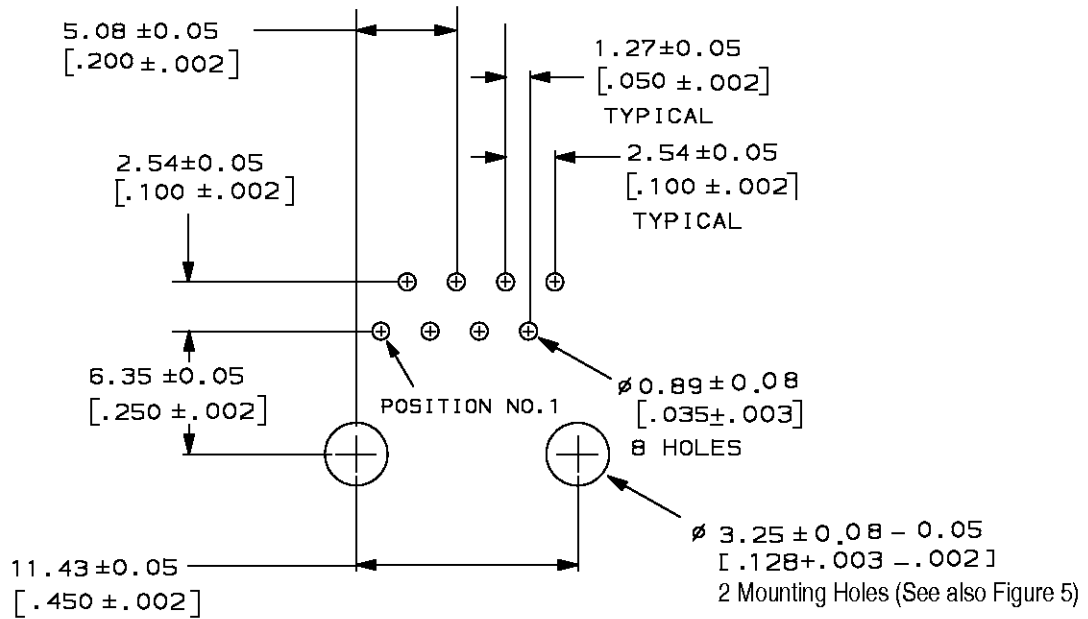


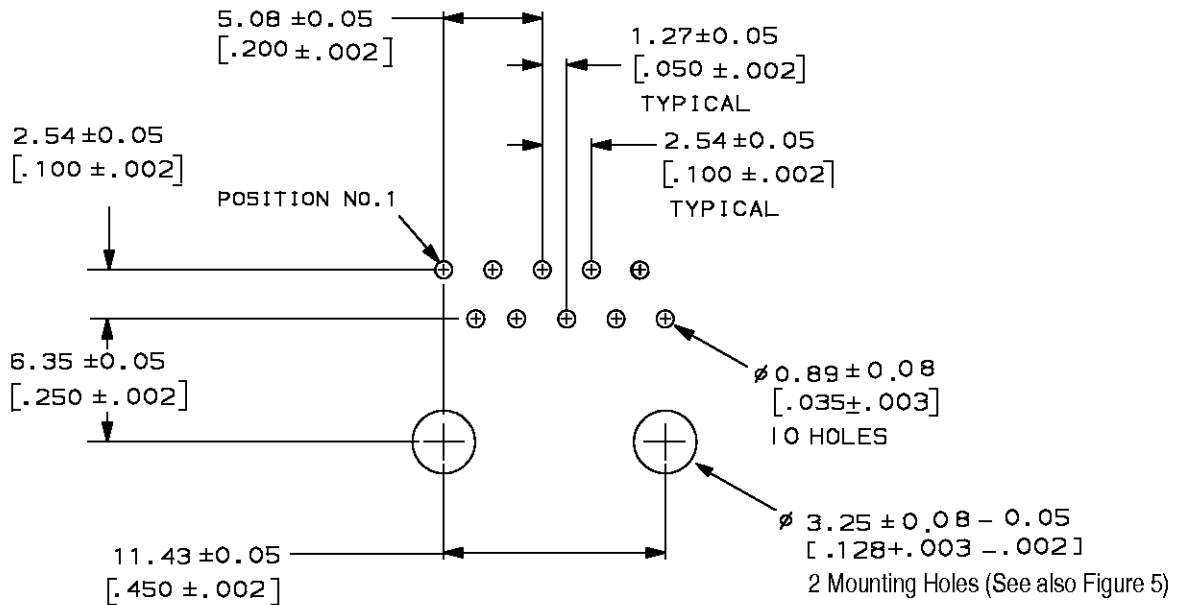
Figure 3 (cont'd)

Component Side of PC Board



Unshielded 8 Position Jacks

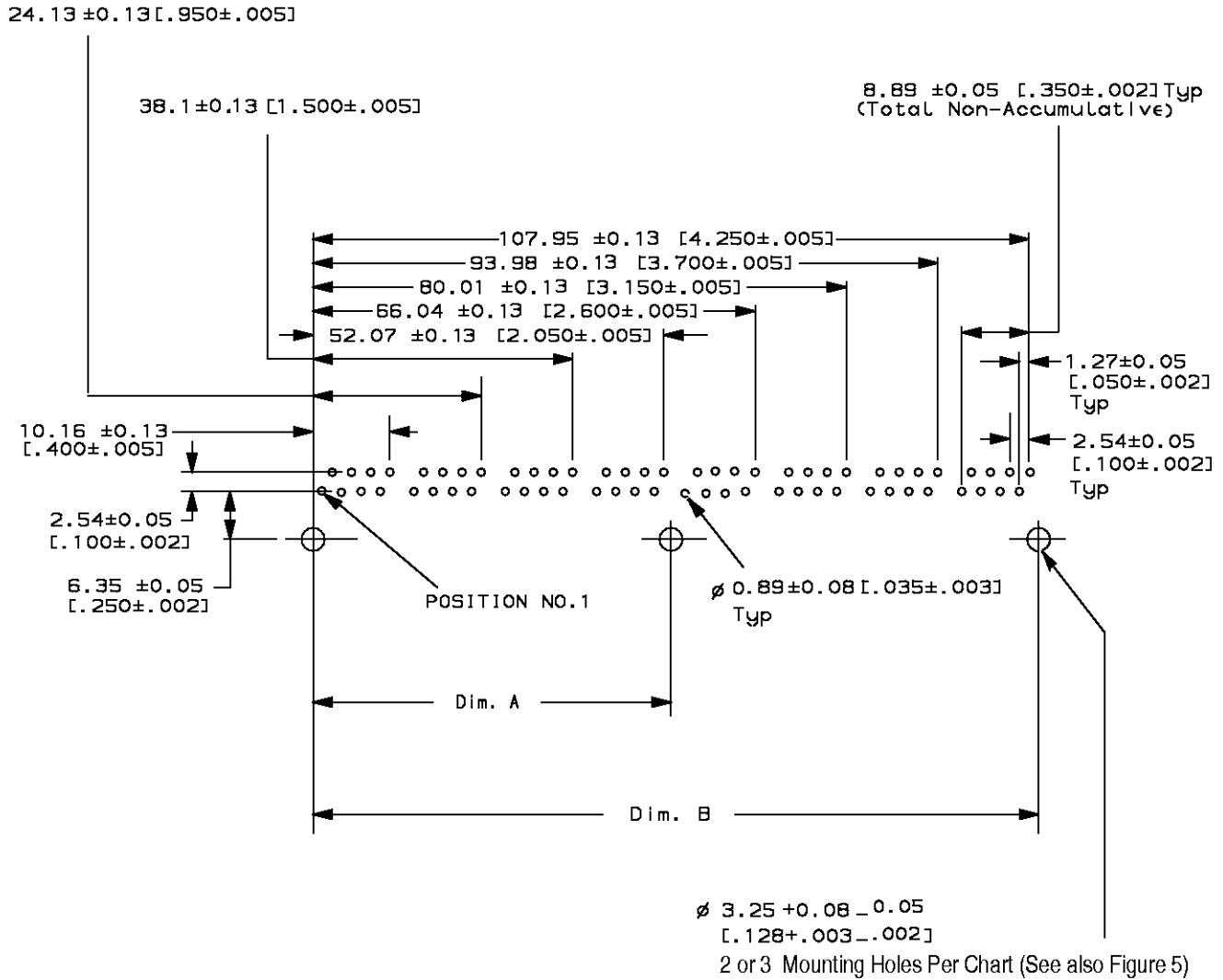
Component Side of PC Board



Unshielded 10 Position Jacks

Figure 3 (cont'd)

Component Side of PC Board



MOUNTING HOLE LOCATIONS		
NUMBER OF PORTS	DIM. A	DIM. B
1	Not Required	11.4 [0.45]
2	Not Required	25.4 [1.00]
3	Not Required	39.4 [1.55]
4	Not Required	53.3 [2.10]
5	Not Required	67.3 [2.65]
6	Not Required	81.3 [3.20]
7	Not Required	95.2 [3.75]
8	54.61 [2.15]	109.2 [4.30]

Unshielded 8 Position Multi-Port Jacks

Figure 3 (end)

B. Shielded Jacks

The hole patterns that apply to all shielded side-entry and top-entry jacks are provided in Figure 4. All pc board layout views shown represent the **component side** of the pc board.

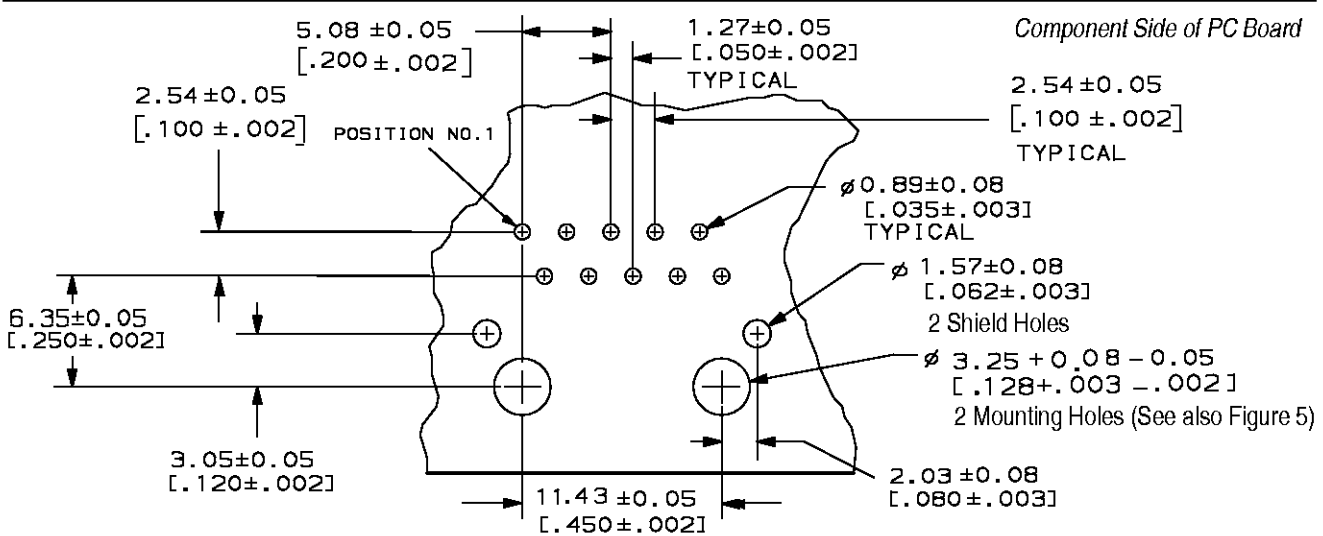
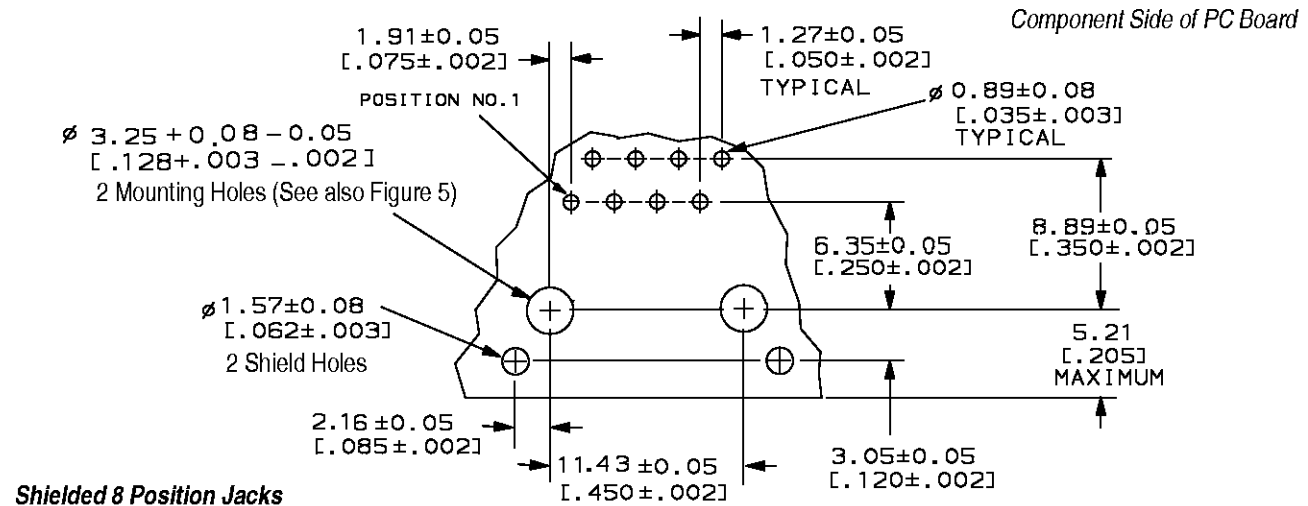
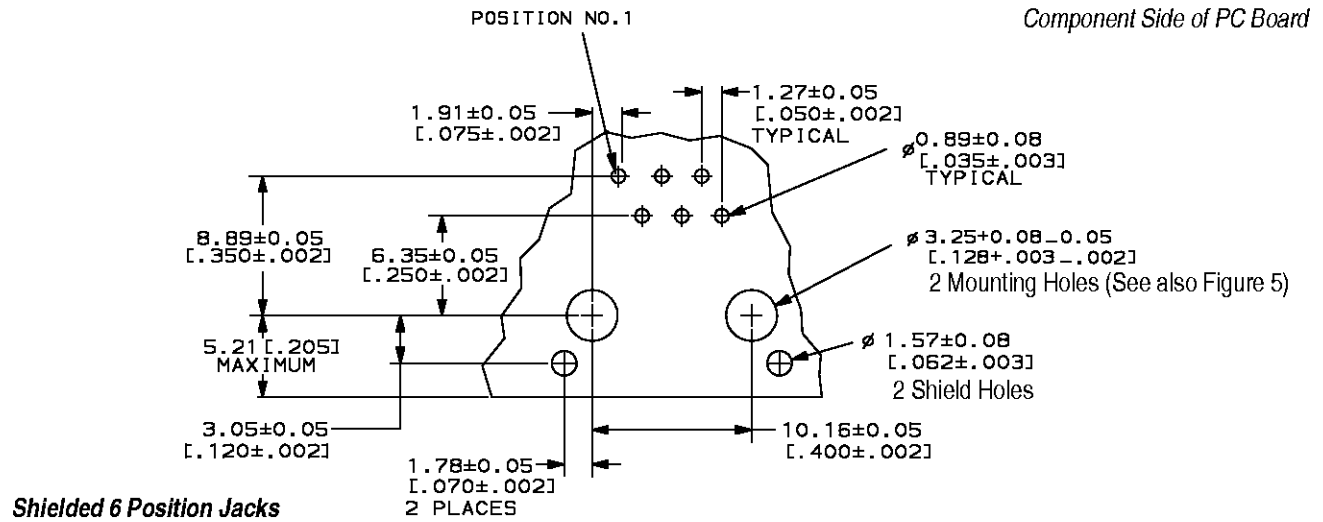
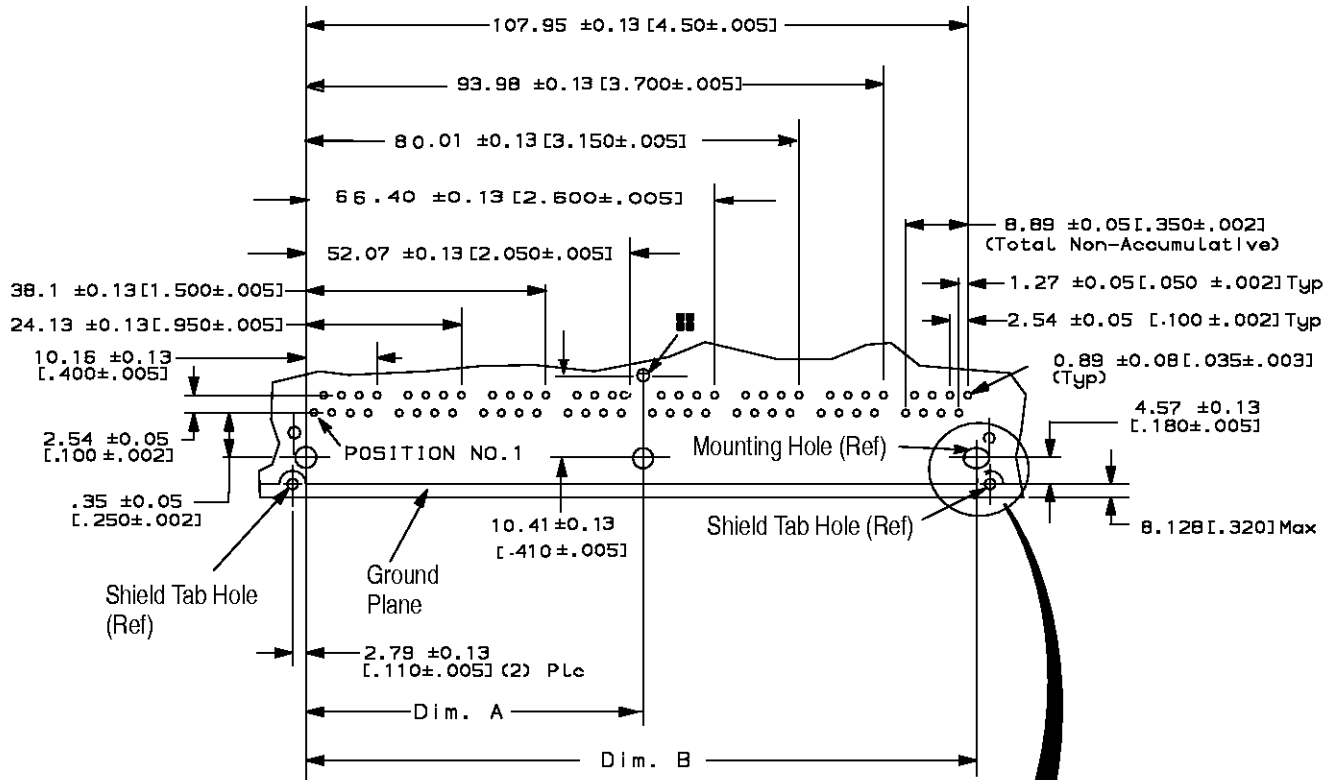


Figure 4 (cont'd)

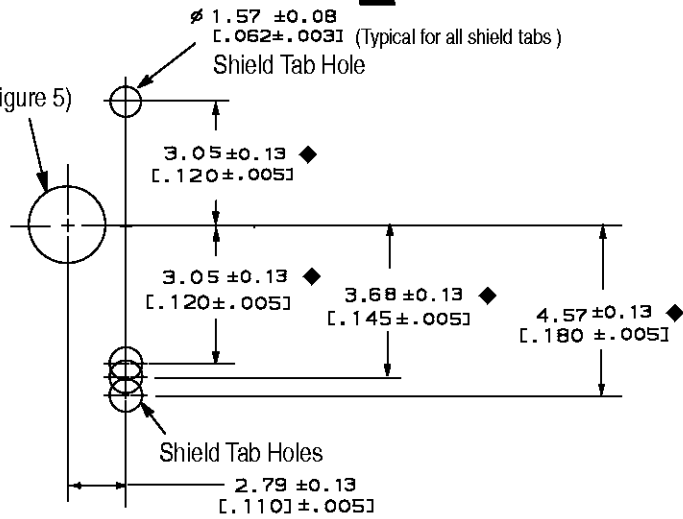
Component Side of PC Board



$\varnothing 3.25 \pm 0.08 - 0.05$ [.128+.003 -.002]
 2 or 3 Mounting Holes Per Chart (See also Figure 5)

$\varnothing 1.57 \pm 0.08$ [.062+.003] (Typical for all shield tabs)
 Shield Tab Hole

MOUNTING HOLE LOCATIONS		
NUMBER OF PORTS	DIM. A	DIM. B
1	Not Required	11.4 [0.45]
2	Not Required	25.4 [1.00]
3	Not Required	39.4 [1.55]
4	Not Required	53.3 [2.10]
5	Not Required	67.3 [2.65]
6	Not Required	81.3 [3.20]
7	Not Required	95.3 [3.75]
8	54.61 [2.15]	109.2 [4.30]



Shield Tab Hole Locations for the Various Multi-Port Jack Assemblies

- Shield tab hole for assemblies with a center ground tab solder tine located at the rear of the shield.
- ◆ Hole location varies among multi-port assemblies and is determined by the dimension from the center of boardlock or guide pin mounting legs to the center of the shield tab solder tine.

Shielded 8 Position Multi-Port Jacks

Figure 4 (end)

3.4. PC Board Contact Tine Holes

Plated through holes must be used for contact solder tines and, when applicable, shield solder tines. The drilled hole size, plating types, and plating thickness are dependent on your application requirements. The finished hole size must be as stated to provide unrestricted insertion, proper retention in the pc board, and to ensure adequate application of solder to the tines. See Figure 5.

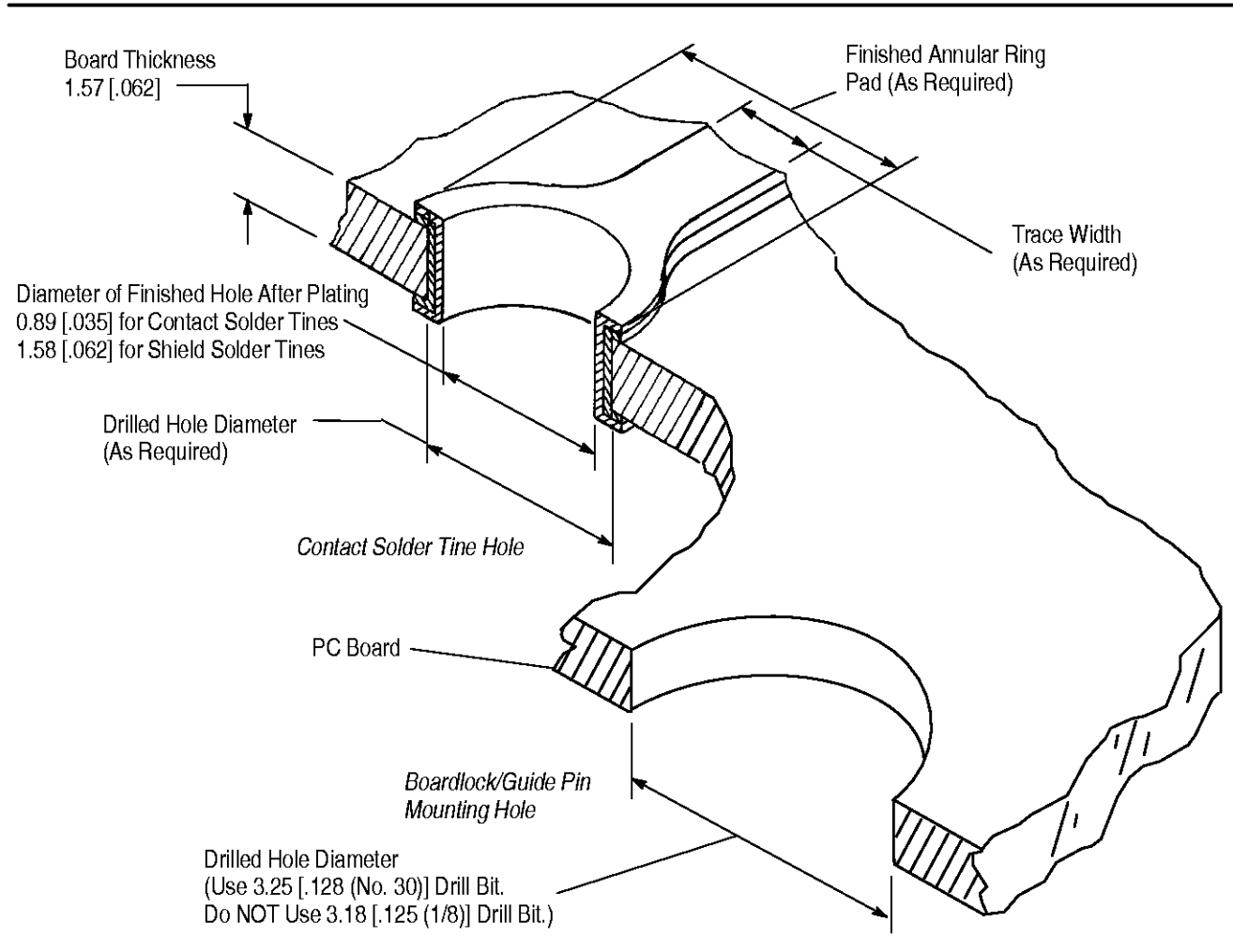


Figure 5

3.5. Alignment

The modular jack shall be flush and evenly seated on the pc board. A hold-down may be used to hold the jack in place during the soldering process.

3.6. Shielding

Shielded modular jacks feature tin/lead plated brass shells which provide continuity for EMC (Electromagnetic Compatibility) applications. When mated with corresponding shielded modular plugs, shielding and grounding continuity are achieved. When the shield solder tines are soldered to the pc board they provide electrical continuity to any ground path on the pc board and, where applicable, panel ground tabs on the shield provide electrical continuity to any ground path through the equipment panel.

3.7. Jack Placement

CAUTION

The modular jacks should be handled only by the housing to avoid deformation, contamination, or other damage to the contact solder tines and, where applicable, shield solder tines.

Determine which hole in the pc board is to receive the number one contact tine, then orient the jack so the number one solder tine is aligned with the hole. Start all solder tines into the board, then press on the top of the jack until it seats on the pc board.

3.8. Soldering

A. Flux Selection

Contact solder tines must be fluxed prior to soldering with a mildly active, rosin base flux. Selection of the flux will depend on the type of pc board and other components mounted on the board. Additionally, the flux must be compatible with the wave solder line, manufacturing, health, and safety requirements. Call the Product Information phone number at the bottom of page 1 for consideration of other types of flux. Some fluxes that are compatible with these modular jacks are provided in Figure 6.

FLUX TYPE	ACTIVITY	RESIDUE	COMMERCIAL DESIGNATION	
			KESTER†	ALPHA‡
Type RMA (Mildly Activated)	Mild	Noncorrosive	186	611

† Product of Kester Solder Co. ‡ Product of Alphametals Inc.

Figure 6

B. Soldering Guidelines

Modular jacks can be soldered using wave or equivalent soldering techniques. We recommend using SN60 or SN62 solder for these connectors. The temperatures and exposure time shall be within the ranges specified in Figure 7.

NOTE The unshielded, 6 position, top-entry, feed through bridging jacks must have an un-terminated plug installed to eliminate pre-load stress and prevent movement of the contacts during the wave soldering process.

SOLDERING PROCESS	TEMPERATURE		TIME (At Max Temp)
	CELSIUS	FAHRENHEIT	
WAVE SOLDERING	260 ⁸⁸	500 ⁸⁸	5 Seconds

⁸⁸ Wave Temperature

Figure 7

C. Cleaning

After soldering, removal of fluxes, residues, and activators is necessary. Consult with the supplier of the solder and flux for recommended cleaning solvents. The following is a listing of common cleaning solvents that will not affect the modular jacks for the time and temperature specified. See Figure 8.

CLEANER		TIME (Minutes)	TEMPERATURES (Maximum)	
NAME	TYPE		CELSIUS	FAHRENHEIT
Alpha 2110■	Aqueous	1	132	270
Bioact EC-7◆	Solvent	5	100	212
Butyl Carbitol●	Solvent	1	Room Ambient	
Isopropyl Alcohol	Solvent	5	100	212
Kester 5778⚡	Aqueous	5	100	212
Kester 5779⚡	Aqueous	5	100	212
Loncoterge 520●	Aqueous	5	100	212
Loncoterge 530●	Aqueous	5	100	212
Terpene Solvent	Solvent	5	100	212

■ Product of Fry's Metals, Inc. ◆ Product of Petroferm, Inc. ● Product of Union Carbide Corp. ⚡ Product of Litton Systems, Inc.

Figure 8

Cleaners must be free of dissolved flux and other contaminants. We recommend cleaning with the pc board on its edge. If using an aqueous cleaner, we recommend standard equipment such as a soak-tank or an automatic in-line machine.

DANGER

Consideration must be given to toxicity and other safety requirements recommended by the solvent manufacturer. Refer to the manufacturer's Material Safety Data Sheet (MSDS) for characteristics and handling of cleaners. Trichloroethylene and Methylene Chloride can be used with no harmful affect to the connectors; however AMP does not recommend them because of the harmful occupational and environmental effects. Both are carcinogenic (cancer-causing) and Trichloroethylene is harmful to the earth's ozone layer.

NOTE

If you have a particular solvent that is not listed, contact the Tooling Assistance Center or Product Information number at the bottom of page 1.

D. Drying

When drying cleaned assemblies and printed circuit boards, make certain that temperature limitations are not exceeded: -40° to 70°C [-40° to 158°F]. Excessive temperatures may cause housing degradation.

3.9. Checking Installed Jack

The modular jack must be seated on the pc board within the dimensions shown in Figure 9.

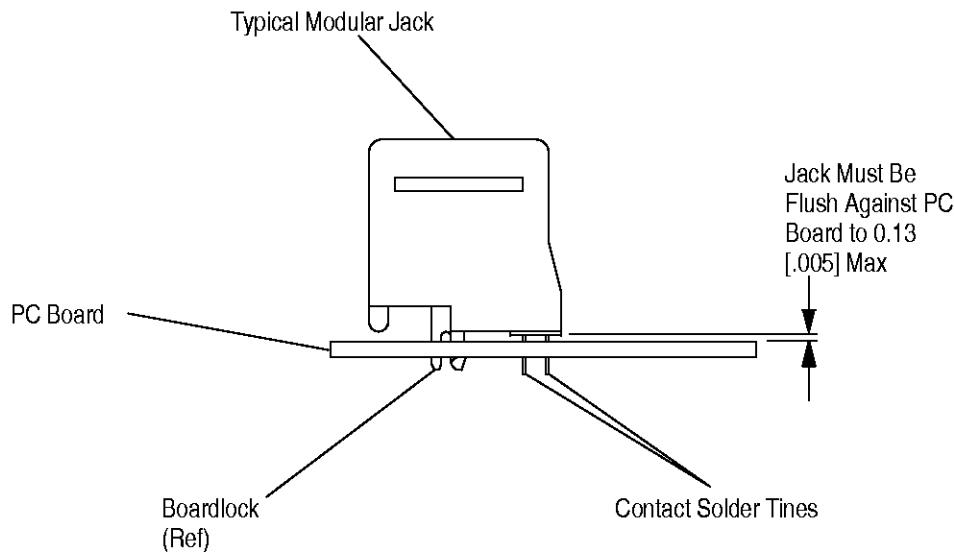


Figure 9

3.10. Repair/Removal

If the jack should become damaged, it must be replaced. It may be removed from the pc board by normal desoldering methods and replaced with a new jack.

CAUTION

When repairing or replacing a modular jack, be careful not to damage other pc board components during the desoldering process.

4. QUALIFICATIONS

AMP Modular Jacks are recognized by Underwriters Laboratories Inc. (UL) under File Number E81956 and certified by the Canadian Standards Association (CSA) under File Number LR7189.

5. TOOLING

No special tooling is required for hand placement of modular jacks onto a pc board. However, a backup support that provides relief for protruding components is needed to prevent deformation of contact solder tines and, when applicable, shield solder tines.

6. VISUAL AID

These illustrations show typical installation applications of AMP Modular Jacks and should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification.

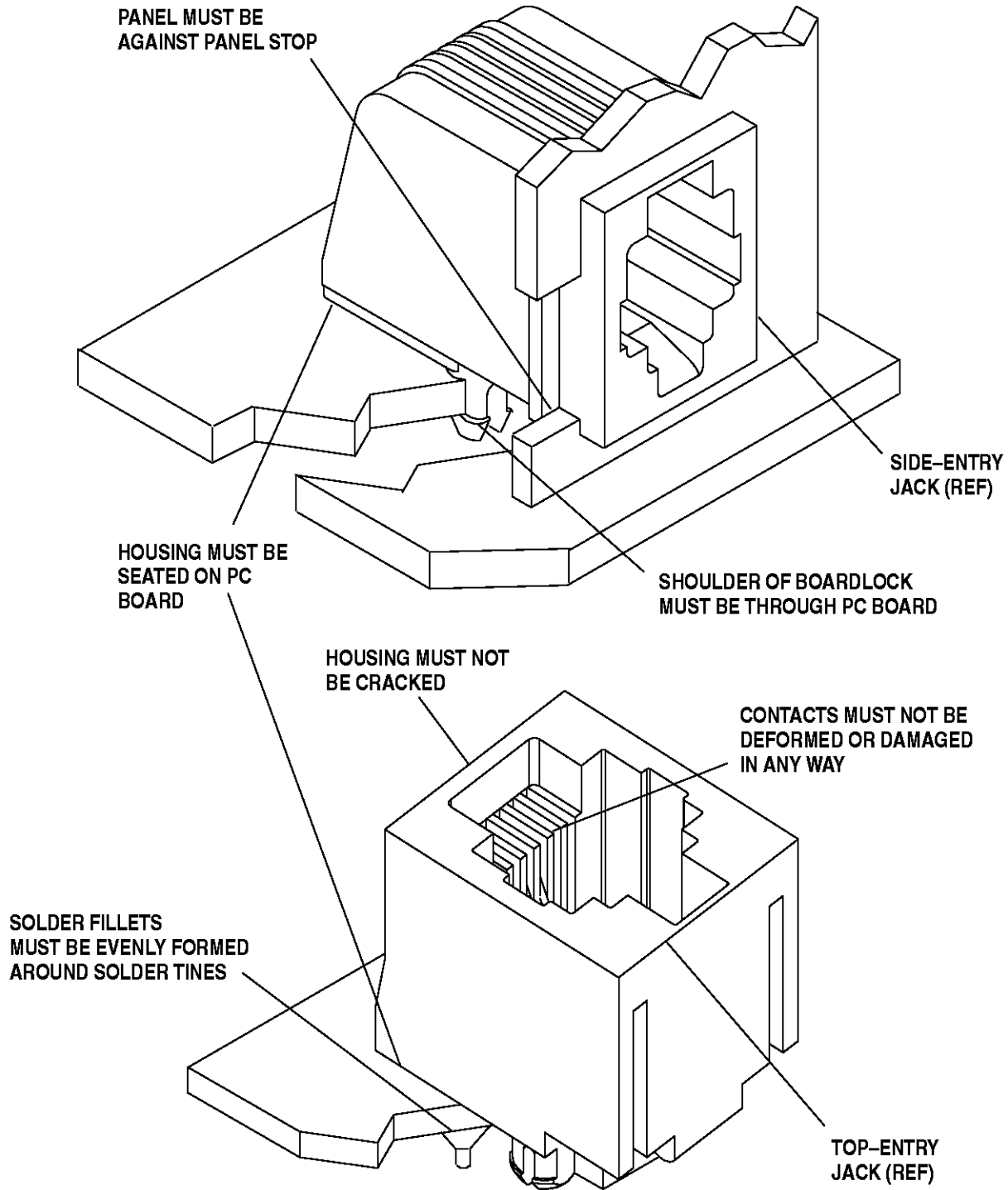


FIGURE 10. VISUAL AID